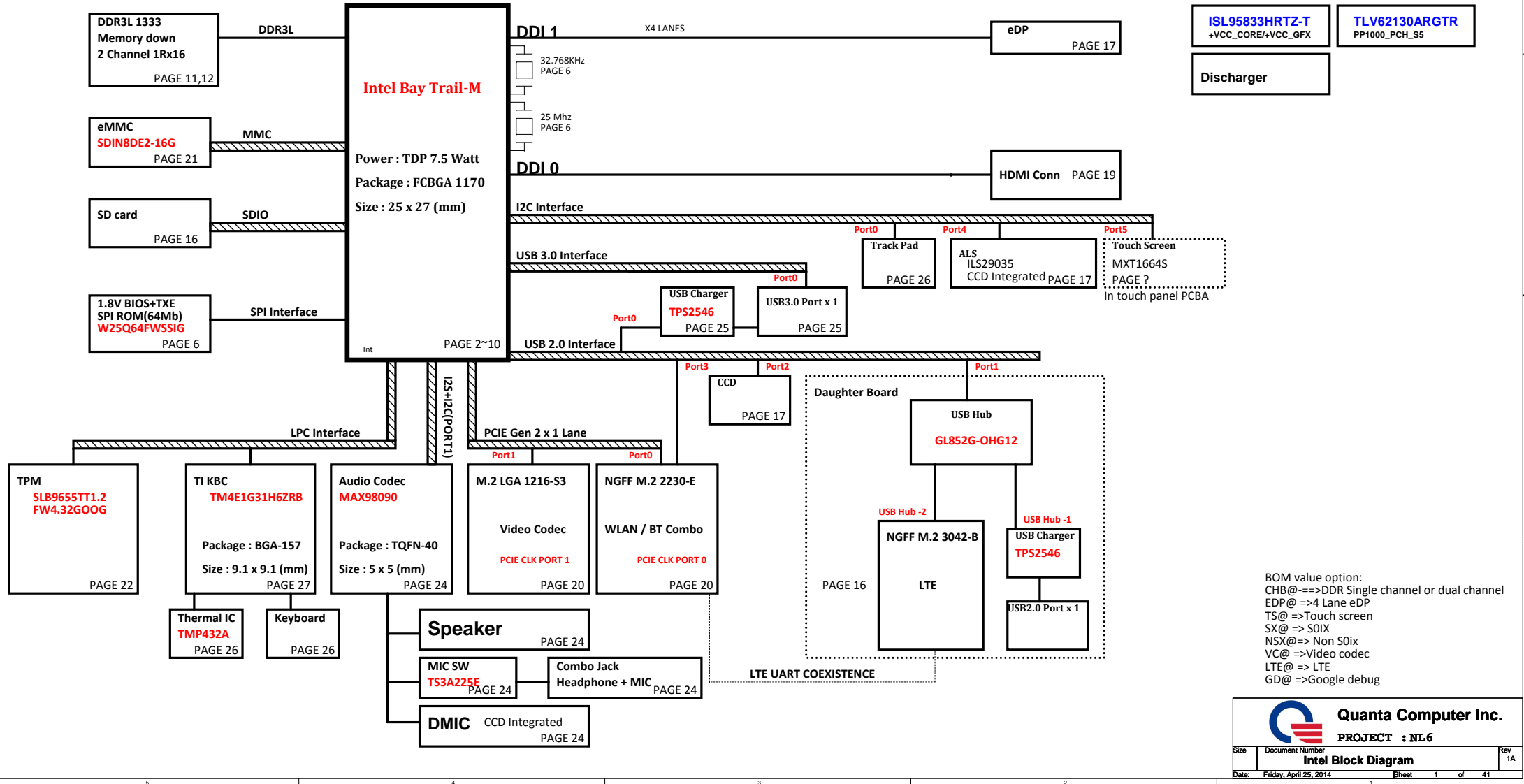
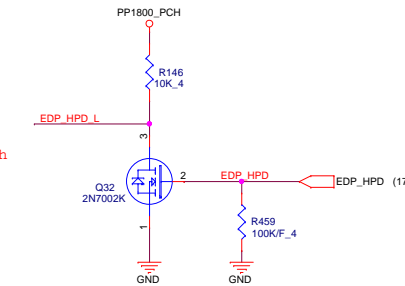



Intel Bay Trail-M Platform Block Diagram

SKUA QC N2930
Up to 1.83 GHz SR1SG(FCBGA) P/N: AJ0QG9UUT01
SKUB DC N2830
Up to 2.17 GHz SR1SG(FCBGA) P/N: AJ0QG9VUT01







<p>1029 unstuff R128, using SoC internal PU</p> <p>1029 unstuff R372, using SoC internal PU</p> <p>1115 stuff R372, system can't boot if un-stuff R372 on proto1.5 board, need intel double confirm before proto2</p>		
<p>1029 unstuff R386, using SoC internal PU</p> <p>1115 stuff R386, it is required for eDP</p>		<p>Quanta Computer Inc.</p> <p>ected</p> <p>PROJECT : NL6</p>
	<p>Size Document Number</p>	<p>Valley 3/9 (Display)</p>
		<p>Rev 1A</p>




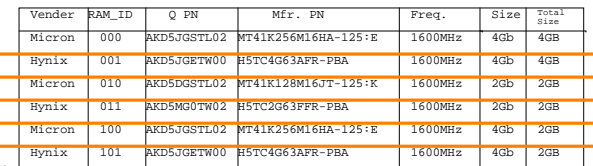
0 = LPC
1 = SPI

I2S_LRCLK (4)
I2S_DOUT (4)

Security Flash Descriptors
0 = Override
1 = Normal Operation

Need check to see if MOSFET isolation needed or not

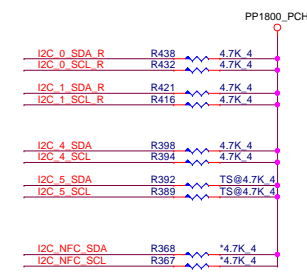
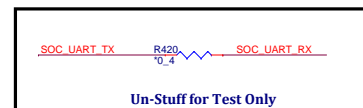
 Quanta Computer Inc. PROJECT : NL6		Rev 1A
Size	Document Number Valley 5/9 (SPI/GPIO/CLK)	
Date: Friday, April 25, 2014	Sheet 6 of 41	



PP1800

SIM_DET C R422 10K 4

TRACKPAD INT DX R433 10K 4

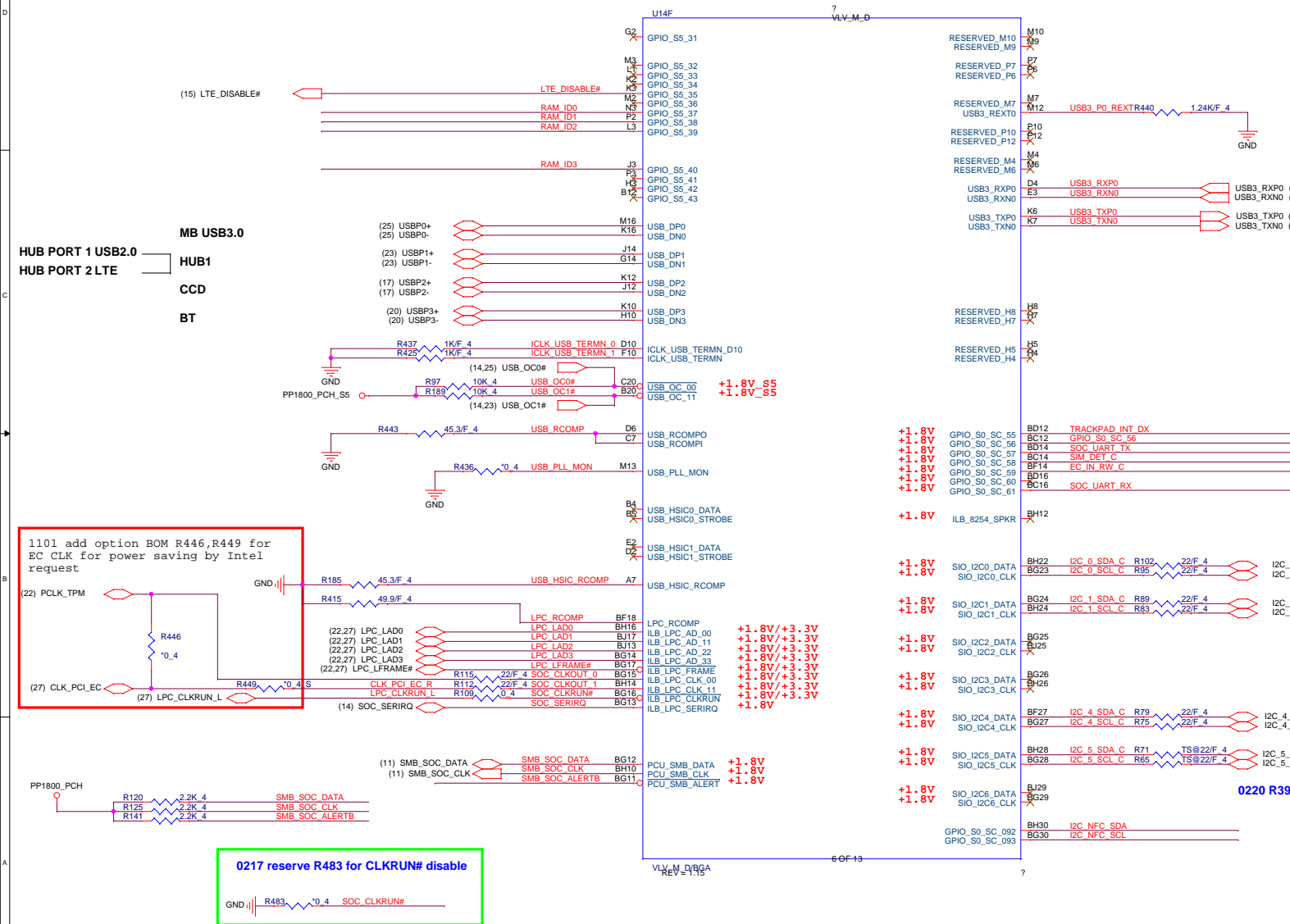


0220 R392,R389,R71,R65 need always to be stuffed even if w/o TS SKU



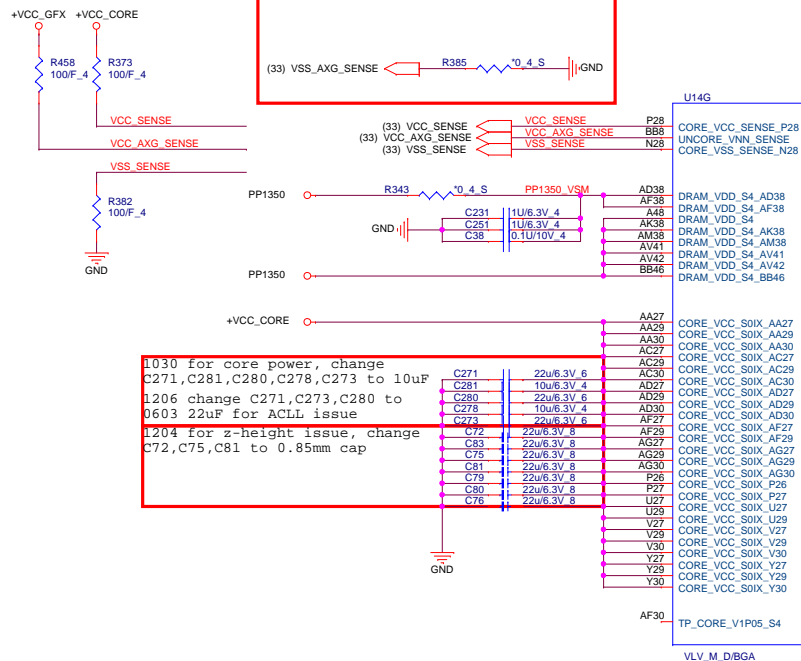
PROJECT : NL6

Size	Document Number	Rev
	Valley 6/9 (USB/LPC/12C)	1A
Date:	Friday, April 25, 2014	Sheet 7 of 41



1031 for layout suggestion by intel, VSS_AXG_SENSE didn't connect to VSS_SENSE, will connect the GND via near VCC_AXG_SENSE
1031 for layout, add 0hm between GND and VSS_AXG_SENSE

(33) VSS_AXG_SENSE \leftarrow R385 \rightarrow 0.4 S \rightarrow GND

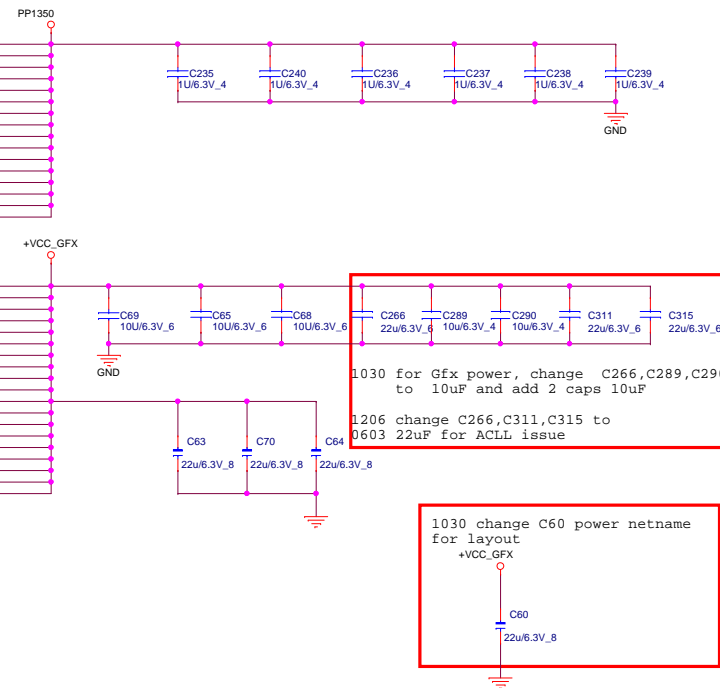


1030 for core power, change C271,C281,C280,C278,C273 to 10uF
1206 change C271,C273,C280 to 0603 22uF for ACLL issue
1204 for z-height issue, change C72,C75,C81 to 0.85mm cap

DRAM_VDD_S4_BD49
DRAM_VDD_S4_BD52
DRAM_VDD_S4_BD53
DRAM_VDD_S4_BF44
DRAM_VDD_S4_BG51
DRAM_VDD_S4_BJ48
DRAM_VDD_S4_C51
DRAM_VDD_S4_D44
DRAM_VDD_S4_F49
DRAM_VDD_S4_F52
DRAM_VDD_S4_F53
DRAM_VDD_S4_H46
DRAM_VDD_S4_M41
DRAM_VDD_S4_M42
DRAM_VDD_S4_V38
DRAM_VDD_S4_Y38

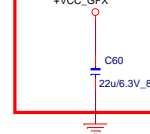
UNCORE_VNN_S3_AA24
UNCORE_VNN_S3_AC22
UNCORE_VNN_S3_AC24
UNCORE_VNN_S3_AD22
UNCORE_VNN_S3_AD24
UNCORE_VNN_S3_AF22
UNCORE_VNN_S3_AF24
UNCORE_VNN_S3_AG22
UNCORE_VNN_S3_AG24
UNCORE_VNN_S3_AJ22
UNCORE_VNN_S3_AJ24
UNCORE_VNN_S3_AK22
UNCORE_VNN_S3_AK24
UNCORE_VNN_S3_AK25
UNCORE_VNN_S3_AK29
UNCORE_VNN_S3_AK30
UNCORE_VNN_S3_AK32
UNCORE_VNN_S3_AM22

REV = 1.15 1031 remove TP44 and TP35 for GND vias adding



1030 for Gfx power, change C266,C289,C290 to 10uF and add 2 caps 10uF
1206 change C266,C311,C315 to 0603 22uF for ACLL issue

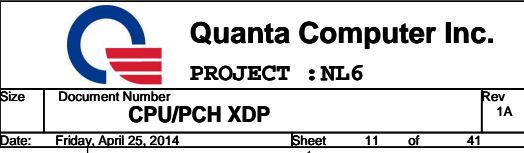
1030 change C60 power netname for layout

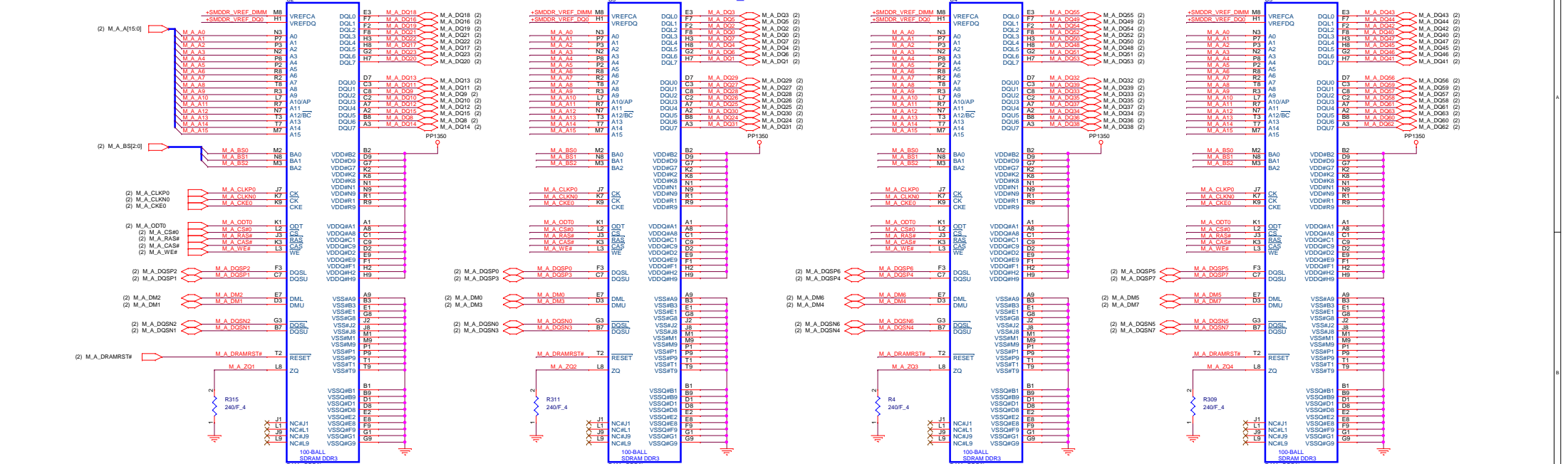


Quanta Computer Inc.
PROJECT : NL6

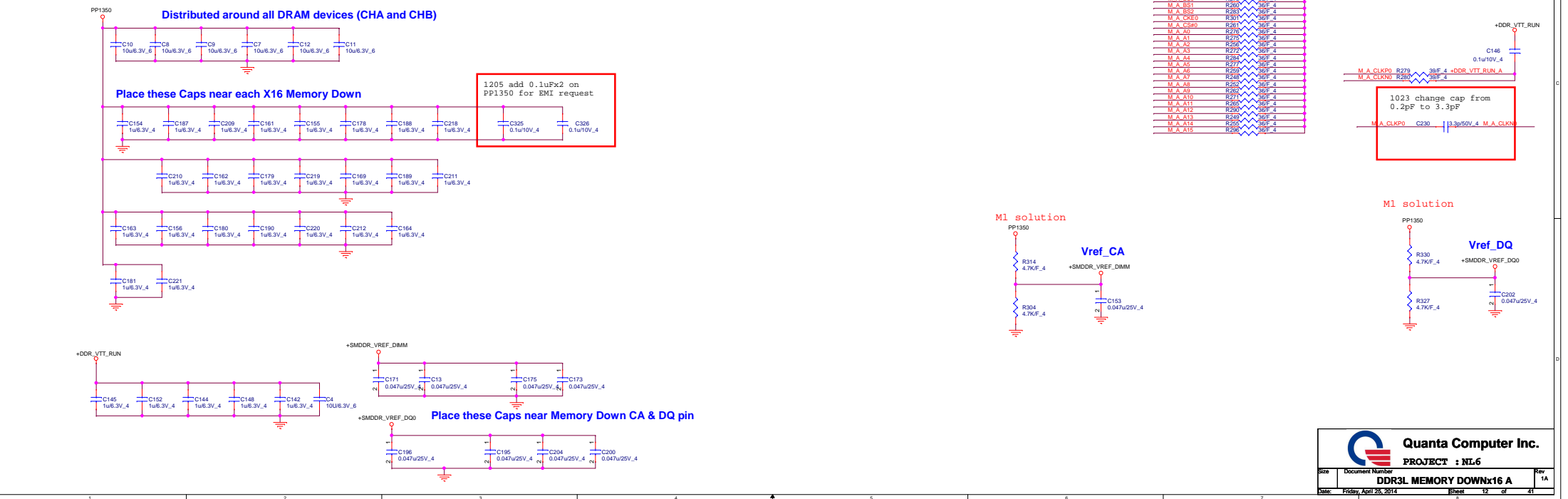
Size Document Number Valley 7/9 (Power 1) Rev 1A
Date: Friday, April 25, 2014 Sheet 8 of 41

11

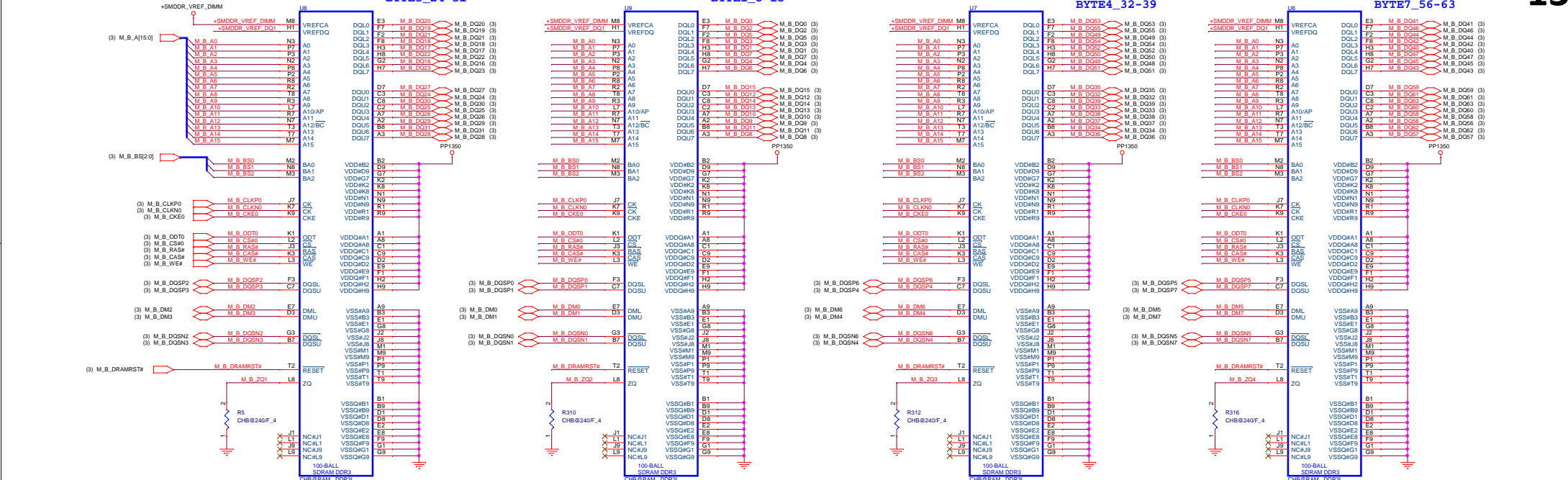




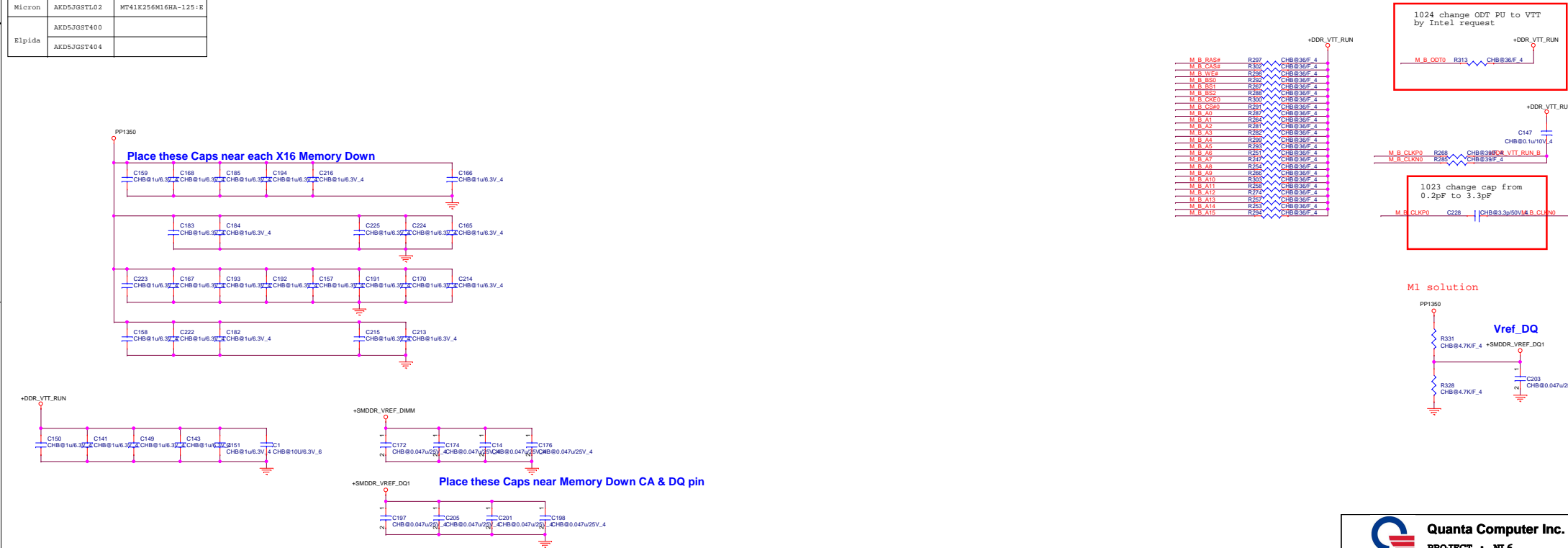
Vendor	P/N
Hynix	AKD5JGST400
Elpida	AKD5JGST404



DATE: 10-11

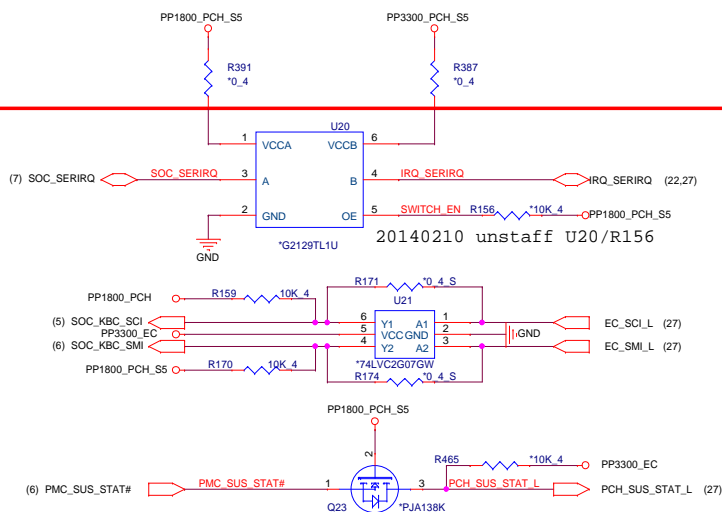


Vendor	P/N	
Micron	AKD5JGSTL02	MT41K256M16HA-125:E
	AKD5JGST400	
Elpida		
	AKD5JGST404	

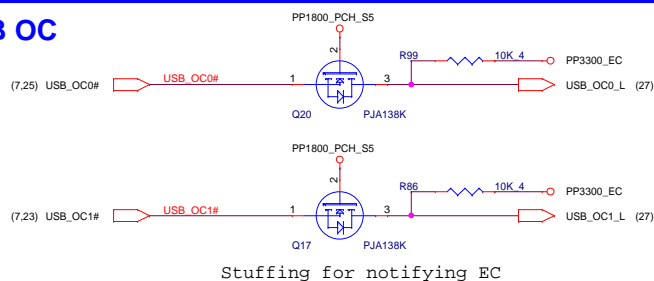


PWRON SEQUENCE

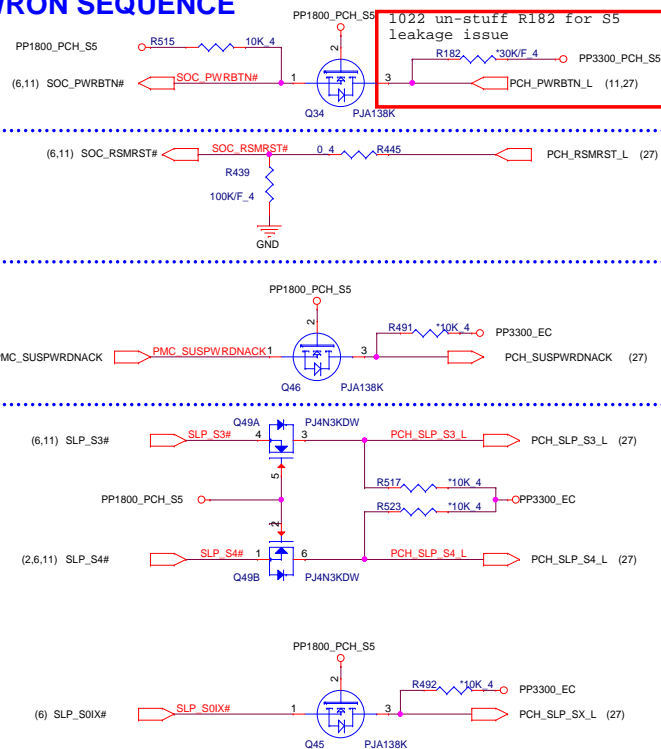
```
9/6 EC table says SERIRQ is OD pin, reserve for debugging
1128 remove R166, because SERIRQ of TPM needs 3V
1128 reserve 0 ohm R387/R391 on VCCA and VCCB for debugging
20140210 unstaff R387/R391
```



USB OC

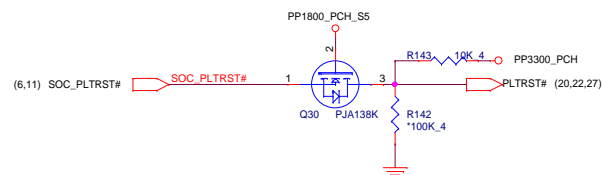


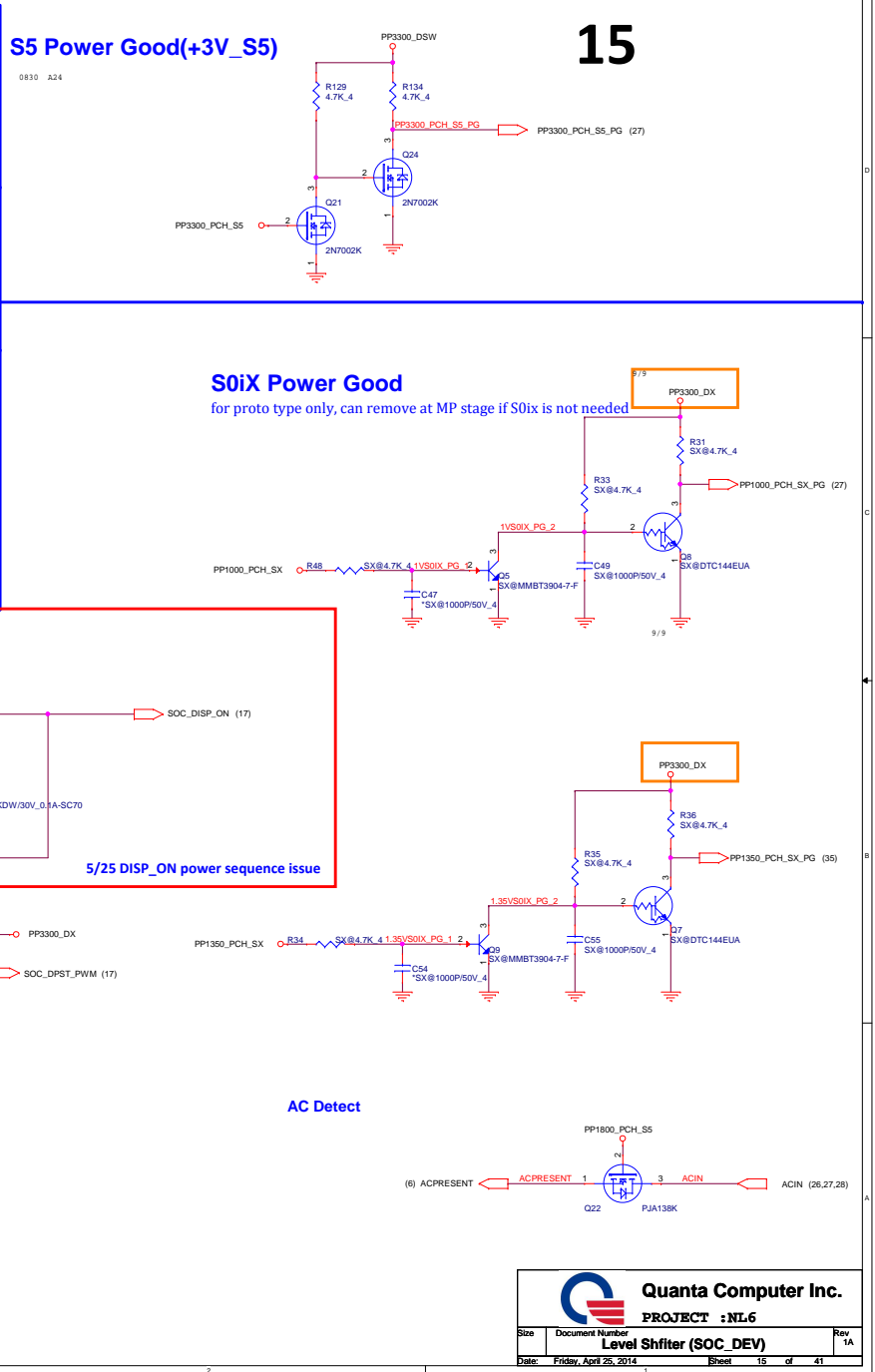
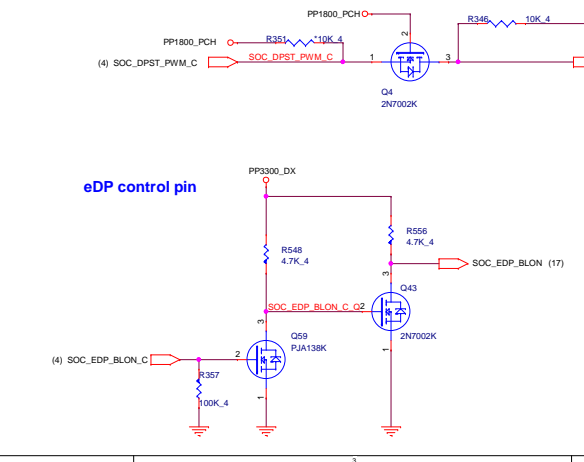
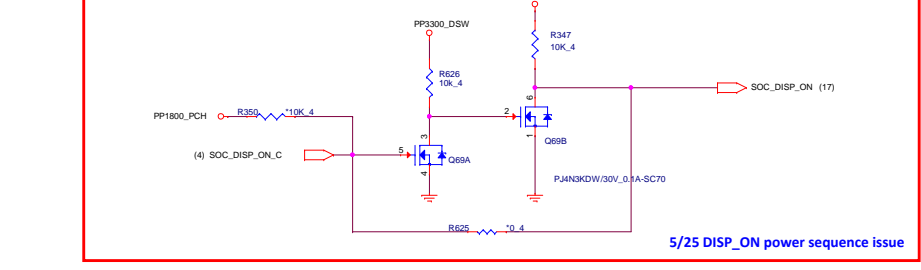
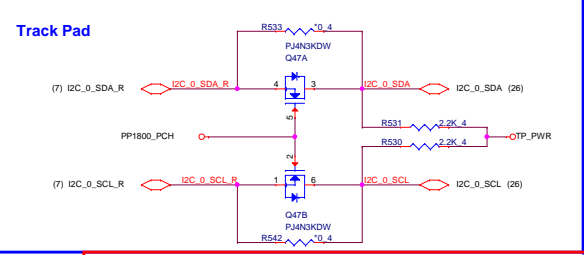
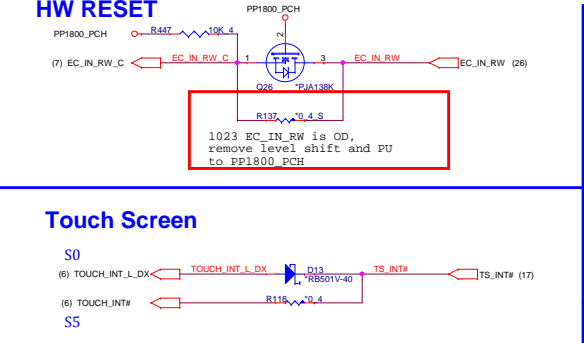
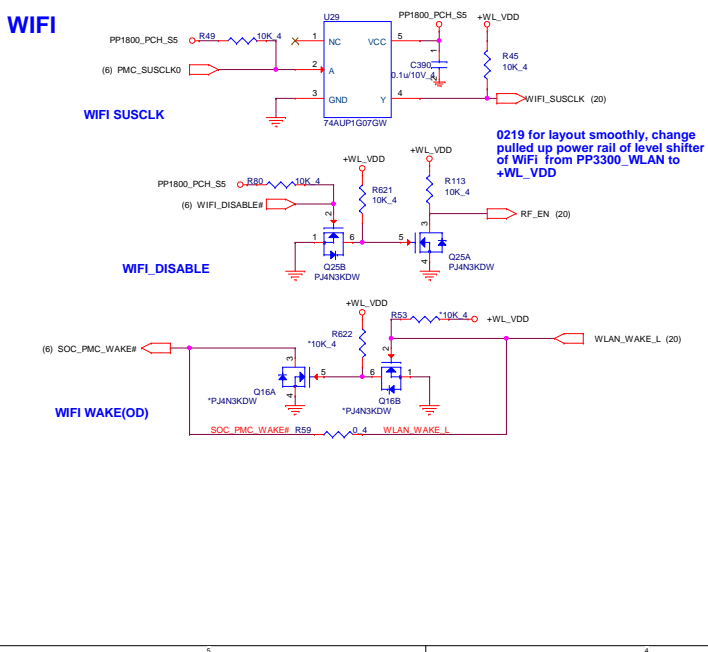
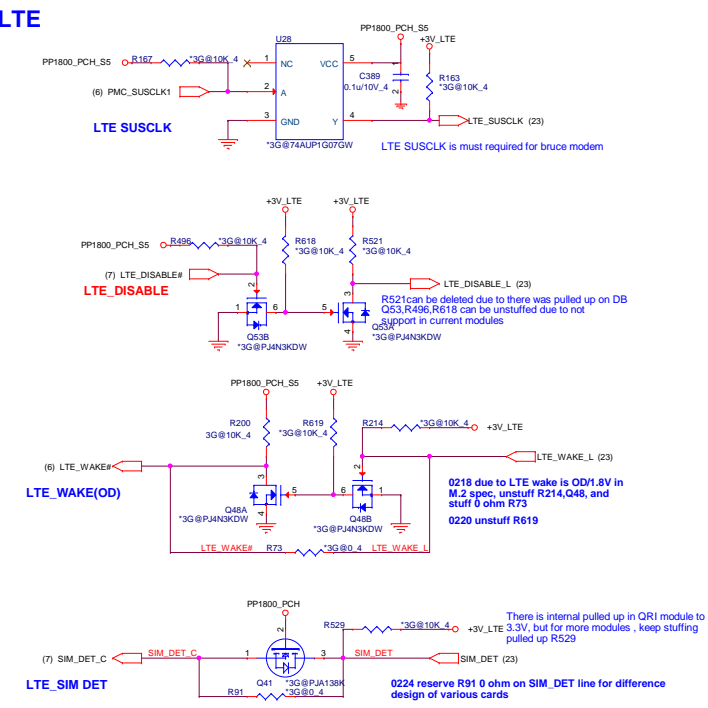
PWRON SEQUENCE



0128 change power rail of Q35,Q36,Q37,Q44 from PP1800_PCH_S5 to PP1800_PCH for PP1800_PCH leakage issue in S3 mode

0206 remove/delete SPI_SIO Interface,
Q35,Q36,Q37,Q44,R486,R484,R485,
R483,R426,R429,R427,R428

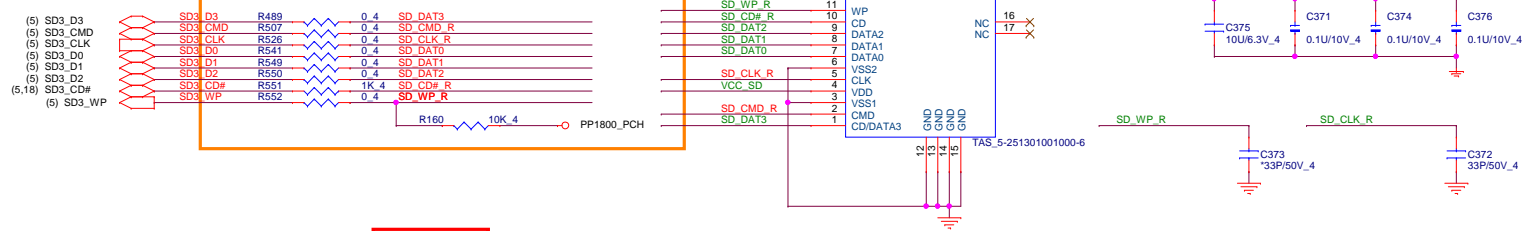




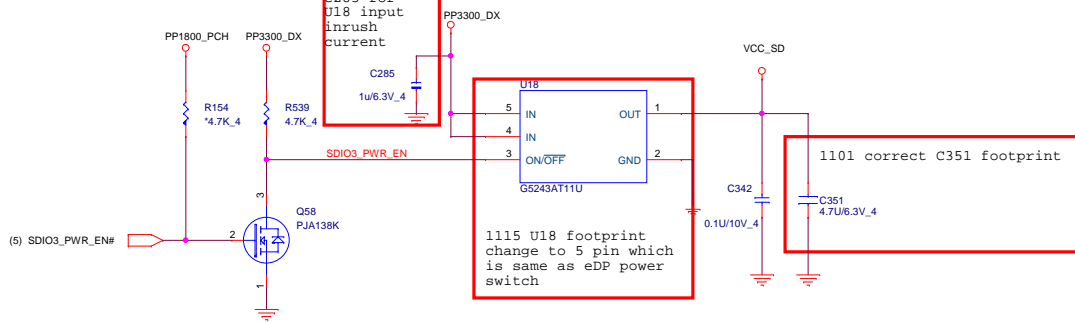
SD/MMC CARD READER CONNECTOR (MMC)

1205 the damping of SDIO change to 0 ohm by Intel request
 1205 add PU for SDIO WP by Intel request
 1205 R551 changes to 1K to isolate SD socket and servo/SoC
 1205 SD3_WP is 1.8V power rail in SoC, change external Pulled up power well of SD3_WP to 1.8V power

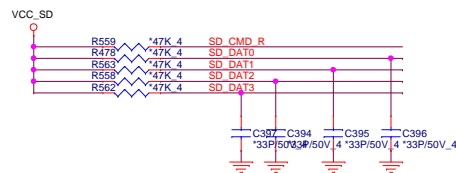
This is full size SD card



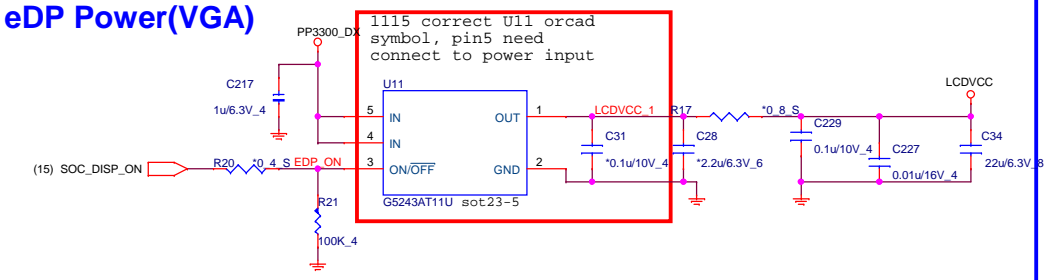
1202 add C285 for U18 input inrush current



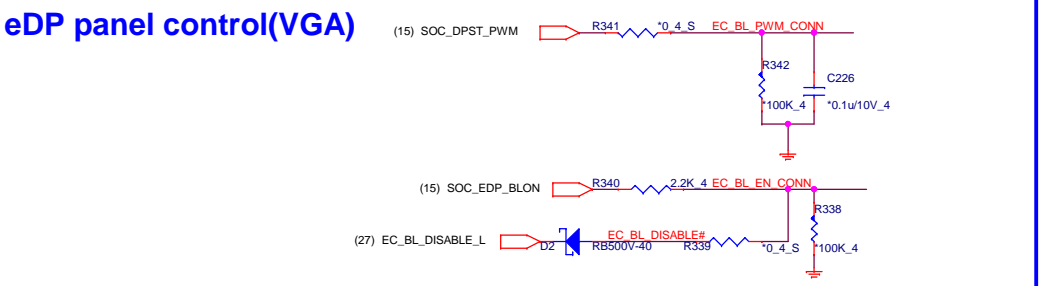
1211 add pulled up resistors on SDIO data/cmd lines
 1212 all pulled up resistors of SDIO data/cmd to be un-stuffed



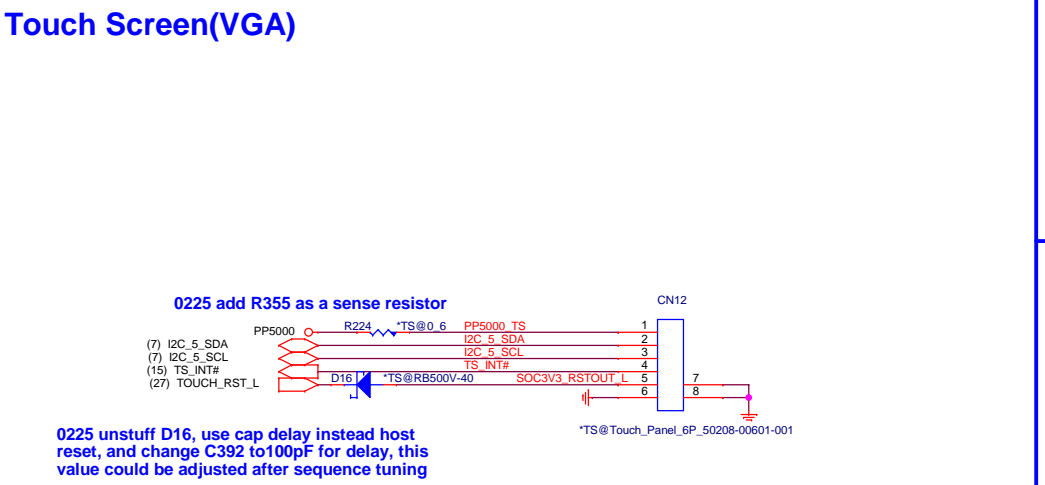
eDP Power(VGA)



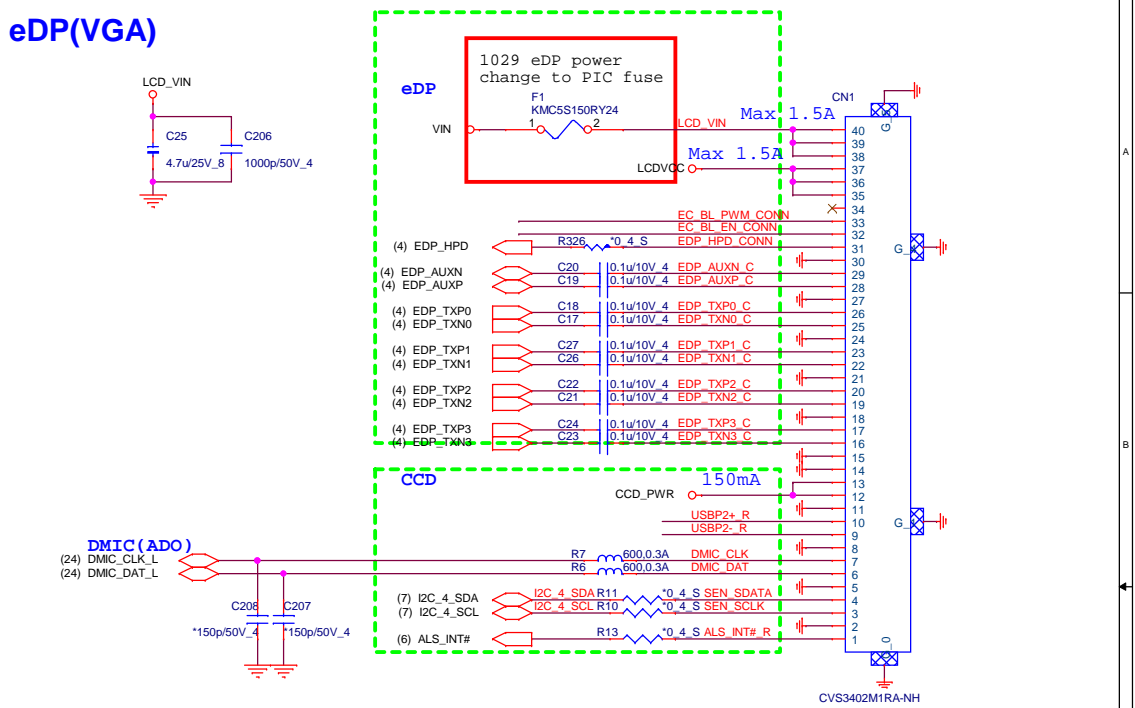
eDP panel control(VGA)



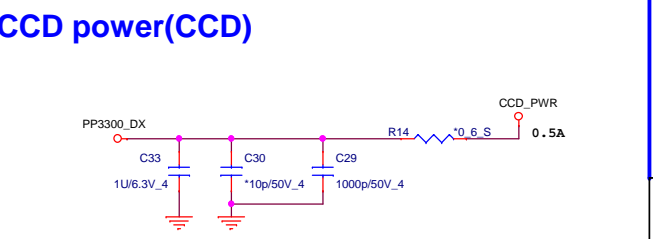
Touch Screen(VGA)



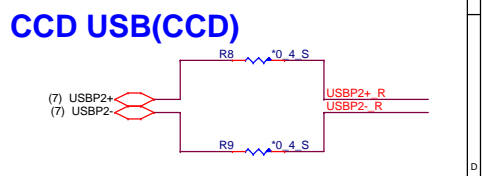
eDP(VGA)



CCD power(CCD)



CCD USB(CCD)



Quanta Computer Inc.

PROJECT : NL6

LVDS/CCD/DMIC/TS

Size	Document Number	Rev
		1A
Date:	Friday, April 25, 2014	Sheet 17 of 41

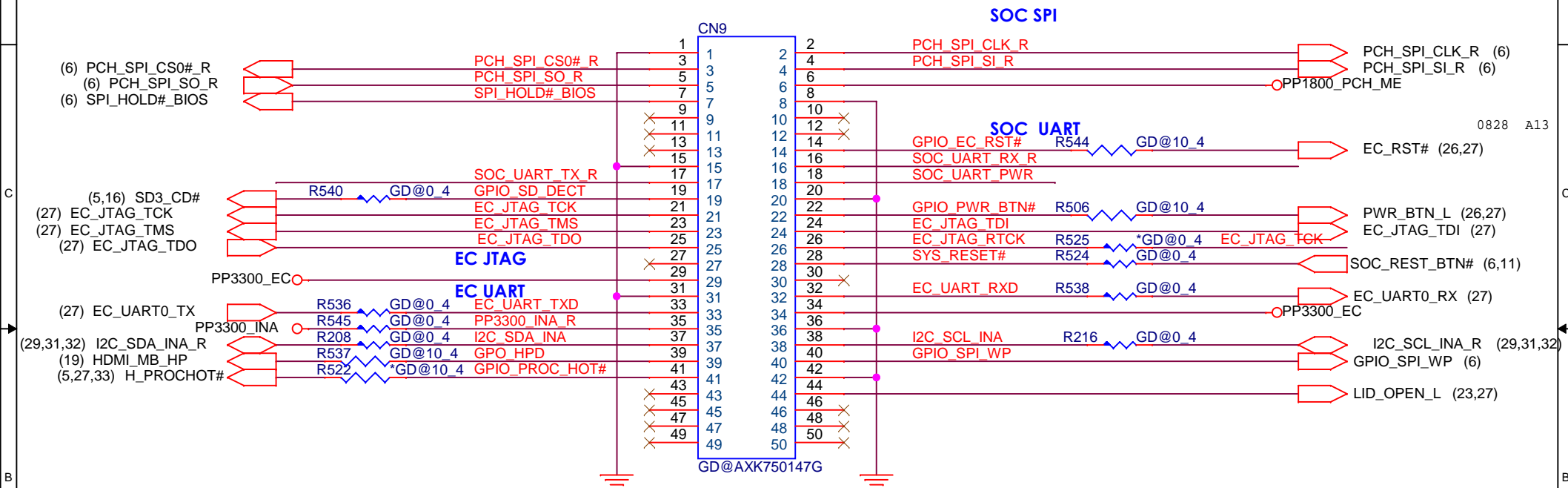
GOOGLE Debug Port(MPC)

50 pin BTB is MUST, don't use 42 pin

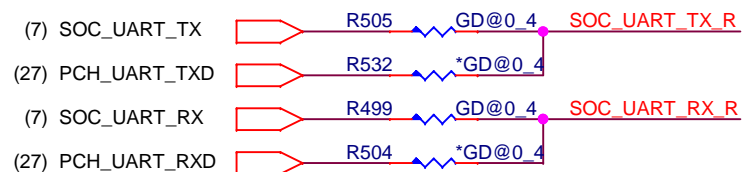
Socket part number AXK750147G

PIN7 OD	PIN39 OD	PIN49 OD
PIN14 OD	PIN41 OD	PIN50 OD
PIN19 OD	PIN43 OD	
PIN22 OD	PIN44 OD	
PIN28 OD	PIN45 OD	
PIN30 OD	PIN46 OD	
PIN37 OD	PIN47 OD	
PIN38 OD	PIN48 OD	

18

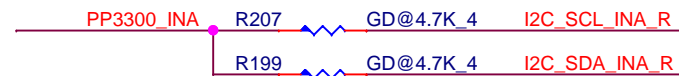


1021 change footprint and PN



9/6 using optional instead of level shifted, default is from SoC

9/13 add pull up

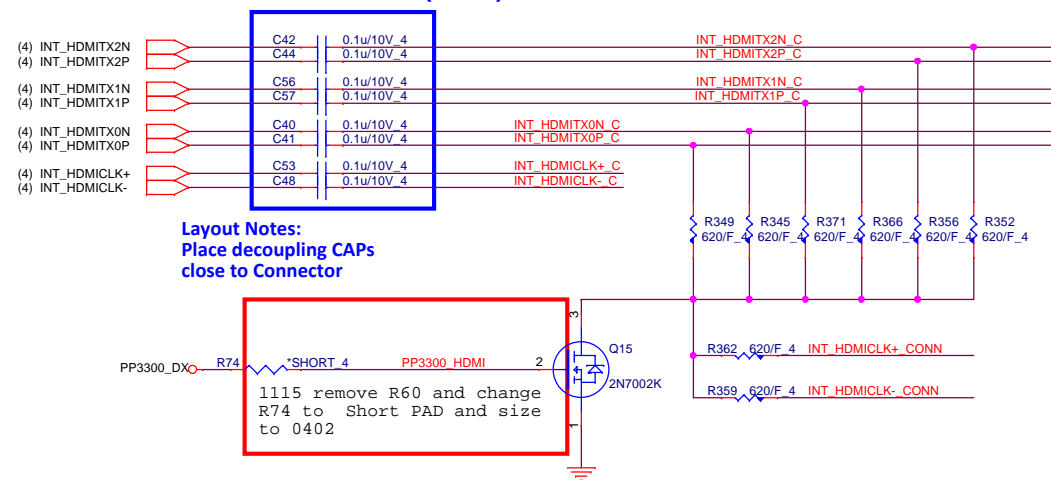


Quanta Computer Inc.

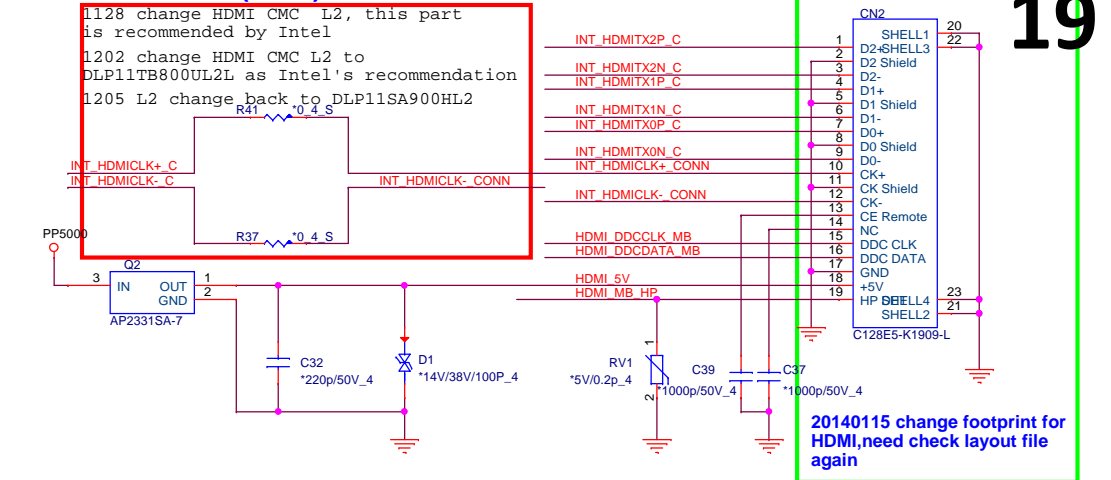
PROJECT : NL6

Size	Document Number	Rev
	Google Debug	1A
Date:	Friday, April 25, 2014	Sheet 18 of 41

HDMI Cost Reduced level shift (HDM)

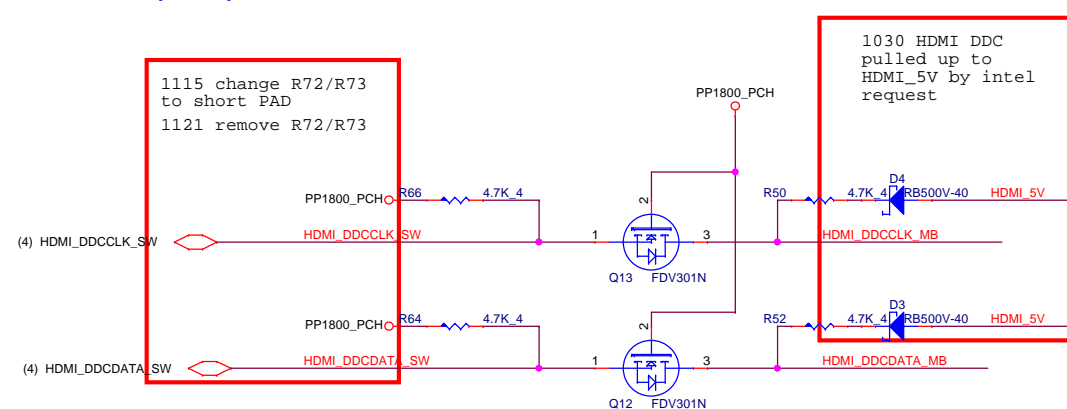


HDMI connector (HDM)

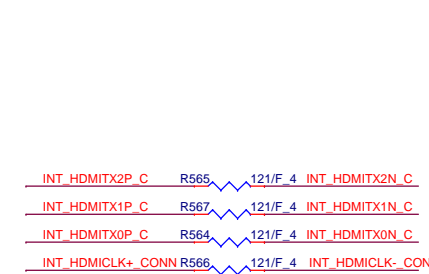


19

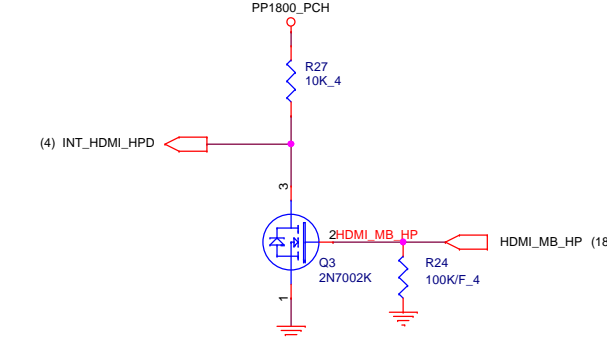
HDMI DDC (HDM)

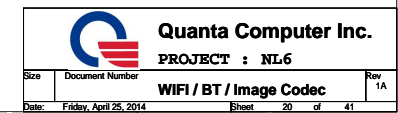


EMI



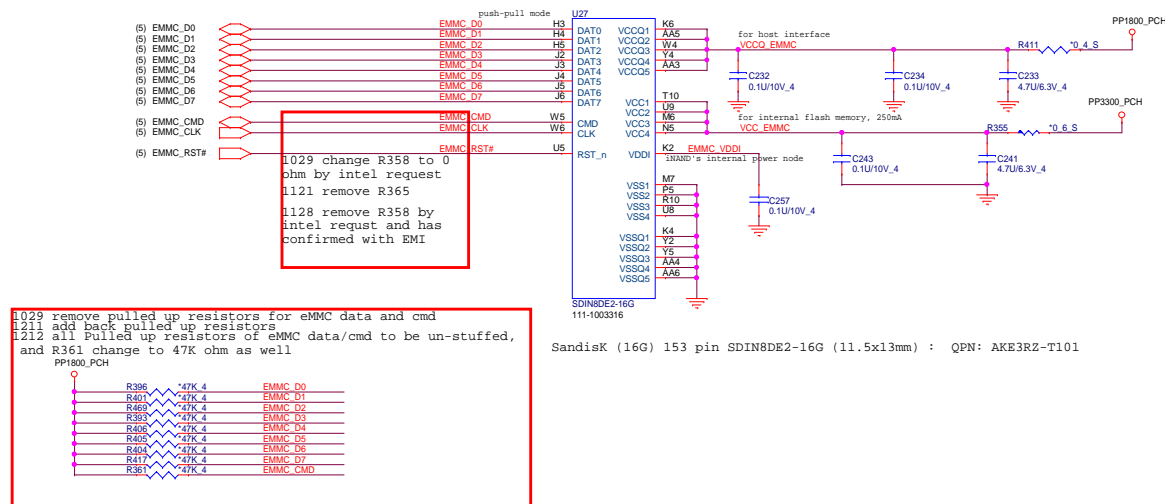
HDMI-detect (HDM)





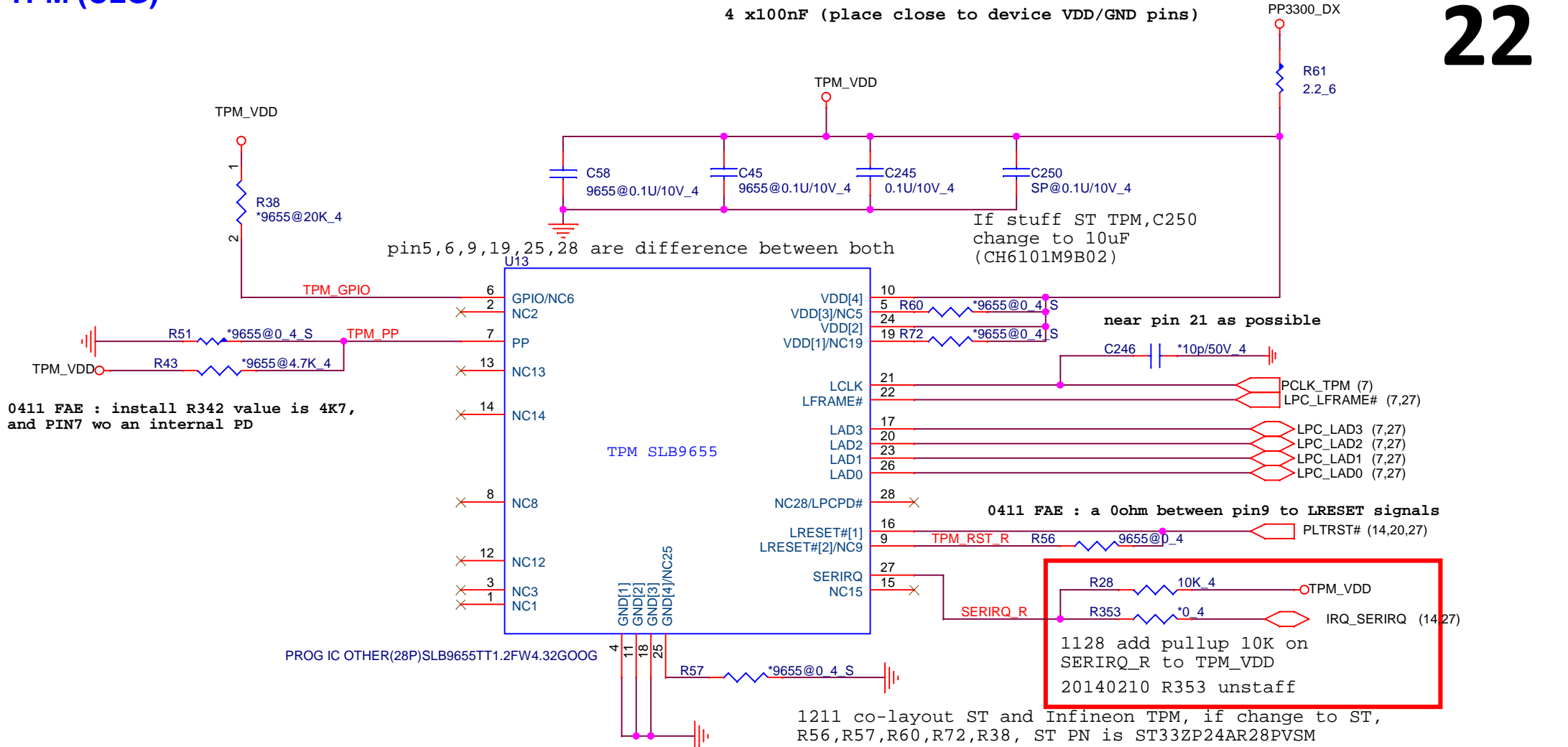
1025 Delete complete SSD(connector and caps)

EMMC (CBS)

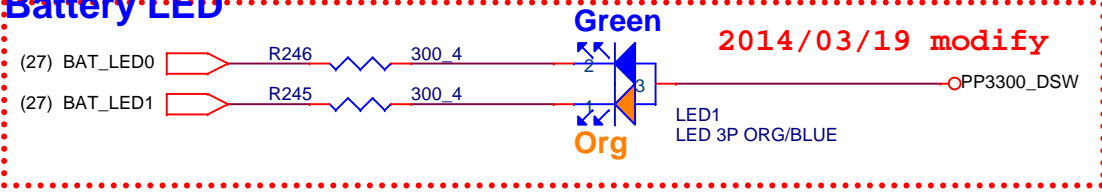


TPM (CLG)

22



LED(UIF) Battery LED



0319 Del Power LED

Quanta Computer Inc.

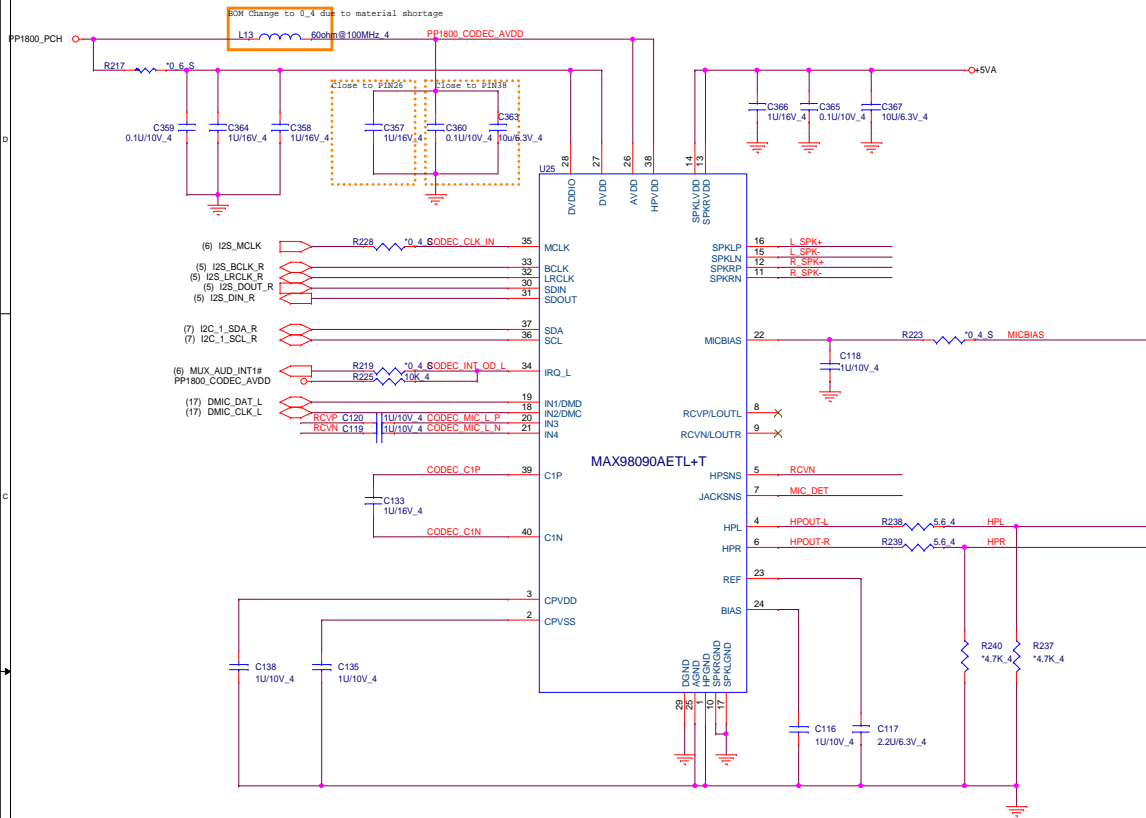
PROJECT : NL6

TPM SLB9655 / LED

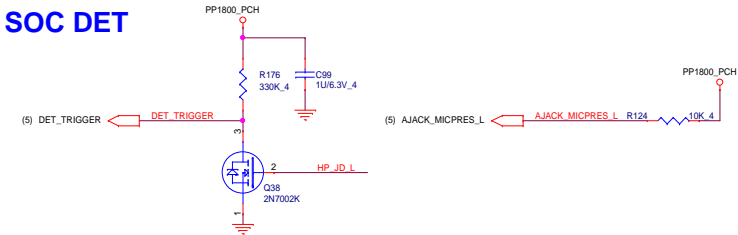
Size Document Number Rev 1A

Date: Friday, April 25, 2014 Sheet 22 of 41

AUDIO CODEC (ADO)



SOC DET

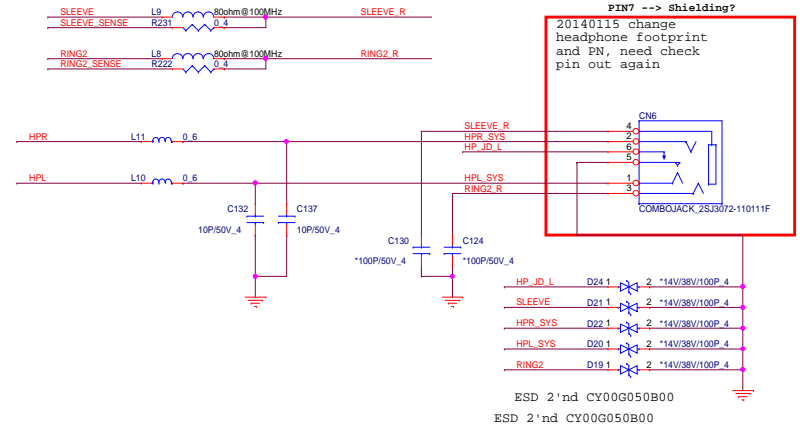


HEADPHONE/Mic combo(ADO)

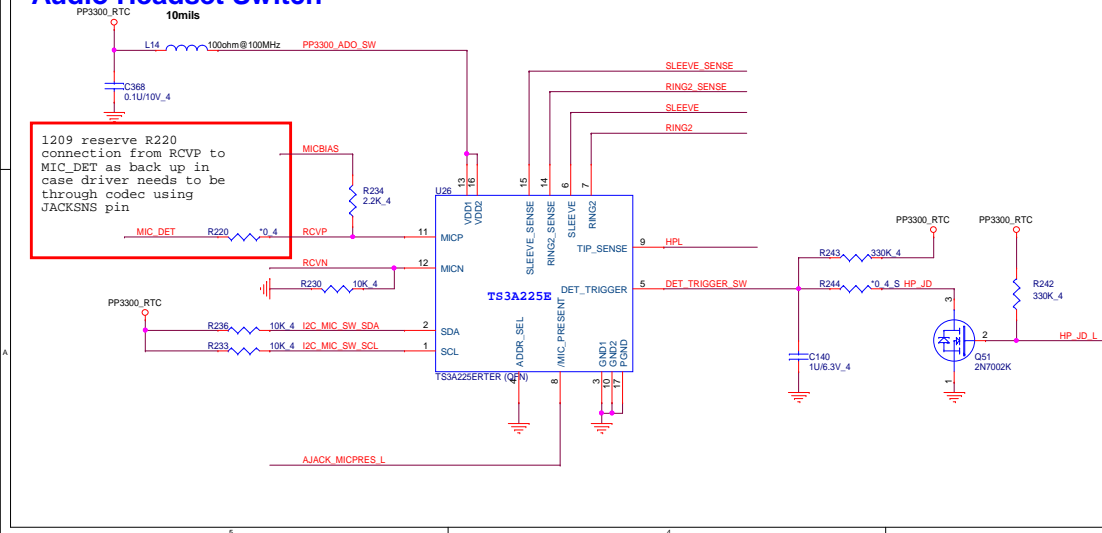
combo jack
Normal open

P/N: DFTJ06FR652
Normal Open
PIN1 --> L?
PIN2 --> R?
PIN3 --> GND/MIC?
PIN4 --> MIC/GND?
PIN5 --> JD?
PIN6 --> GND?
PIN7 --> Shielding?

20140115 change
headphone footprint
and PH, need check
pin out again



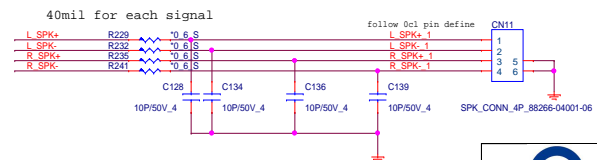
Audio Headset Switch



Codec PWR 5V(ADO)



Internal Speaker



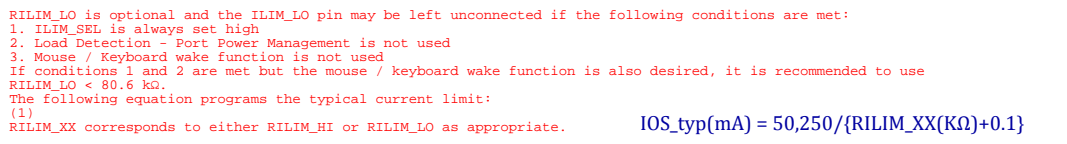
Quanta Computer Inc.

PROJECT : NL6

Size	Document Number	Rev
	MAX98090/HP/SPK	1A

Date: Friday, April 25, 2014 Sheet 24 of 41

25

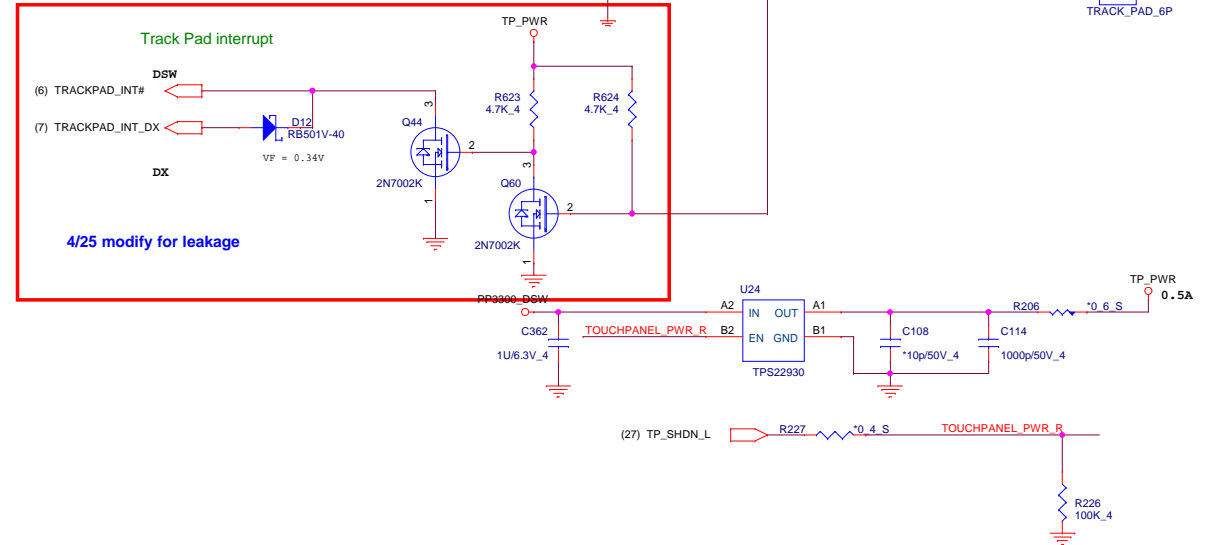
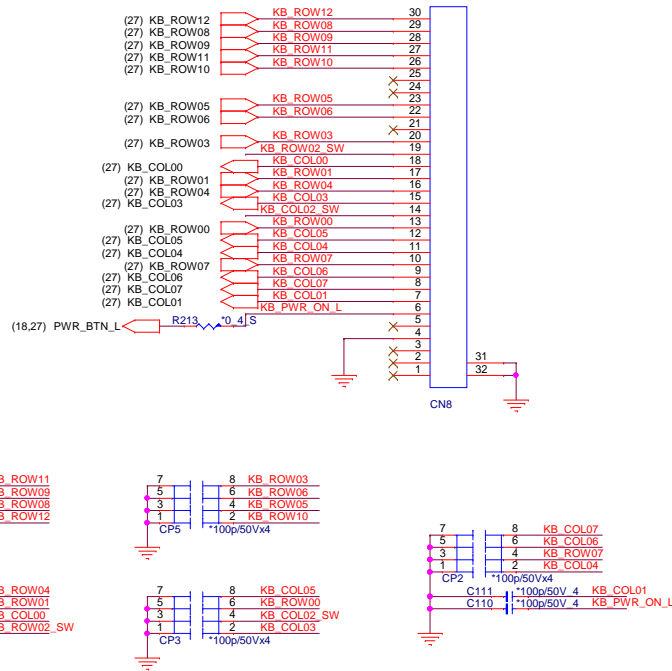
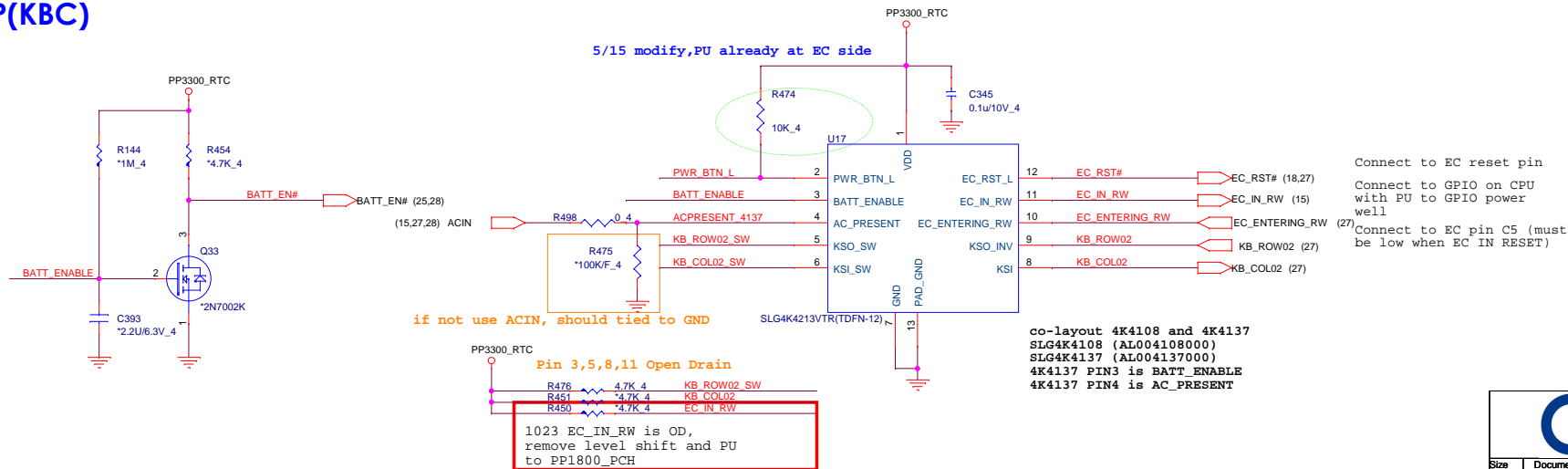


0218 reserve C330 for EMI request

Track PAD BOARD CONN (TPD)

20140127 Change KB CONN for ME require

KB_CONN_51518-03001-001

HOLELESS RESET
2-CHIP(KBC)

Connect to EC reset pin
Connect to GPIO on CPU
with PU to GPIO power
well
Connect to EC pin C5 (must
be low when EC IN RESET)

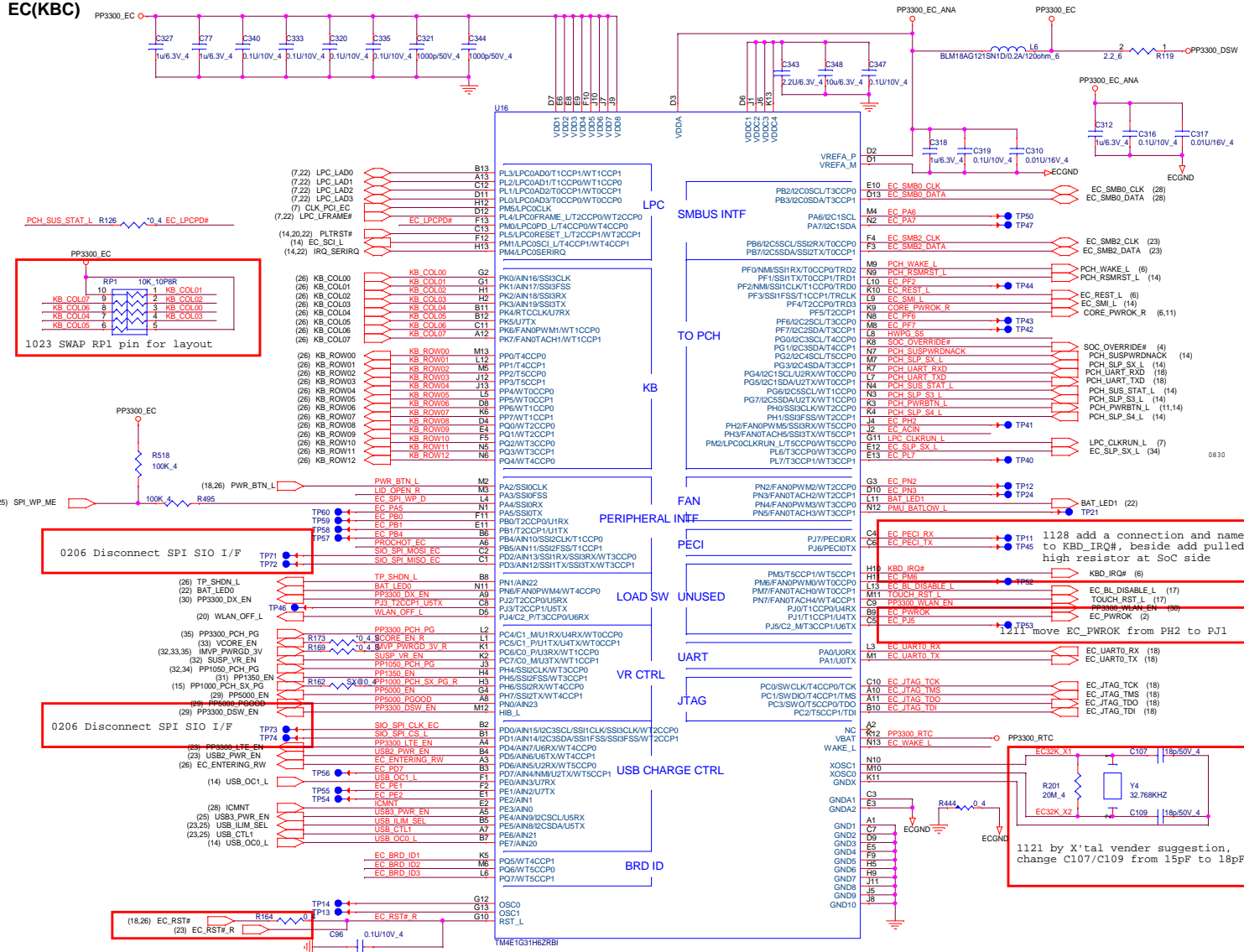
co-layout 4K4108 and 4K4137
SLG4K4108 (AL004108000)
SLG4K4137 (AL004137000)
4K4137 PIN3 is BATT_ENABLE
4K4137 PIN4 is AC_PRESENT



Quanta Computer Inc.

PROJECT : NL6

Size	Document Number	Rev
	KB/TP/FAN/HW Reset	1A
Date:	Friday, April 25, 2014	Sheet 26 of 41



SM BUS ARRANGEMENT TABLE

SM Bus 0	BATT and CHARGER
SM Bus 1	NA
SM Bus 2	THERMAL SENSOR

Add diode for leakage issue



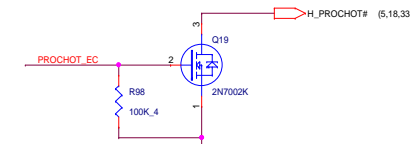
SM BUS/I2C PU(KBC)

BATT and CHARGER / LCD BL

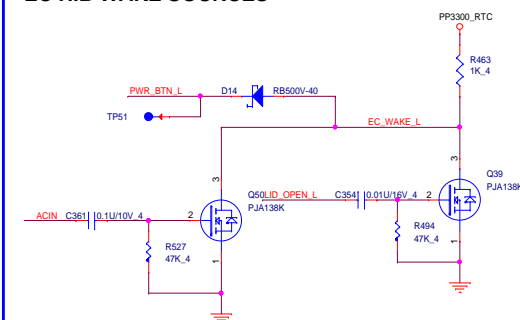


1030 Thermal IC VDD has two option, one is PP3300_DSW(=PP3300_EC), another is PP3300_DX, default is stuffing to DSW rail

THERMAL SENSOR



EC HIB WAKE SOURCES



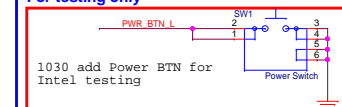
HWPG(KBC)



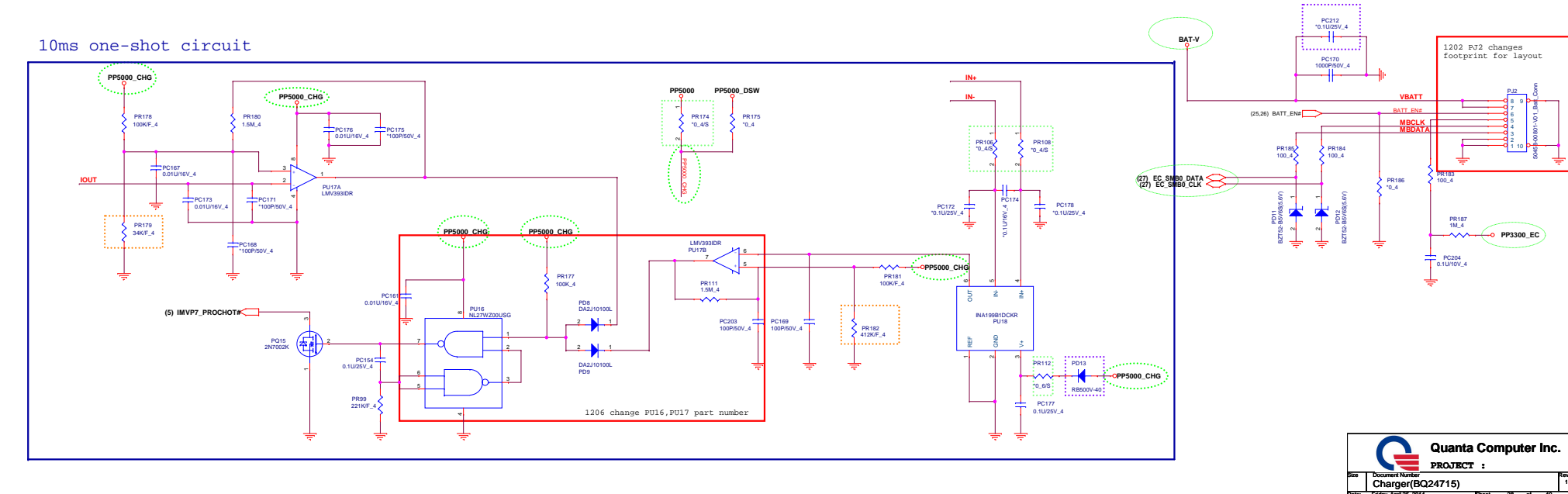
OD pin list

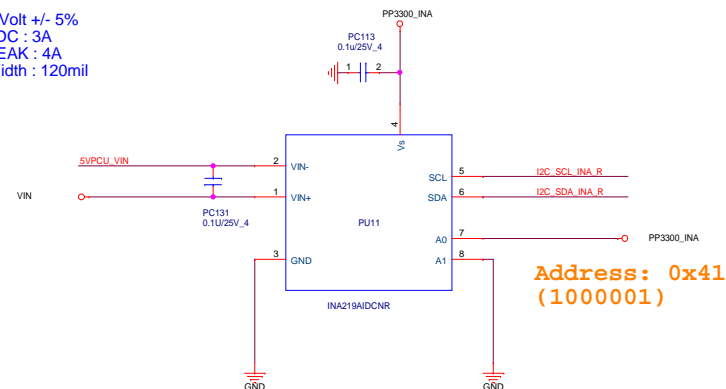
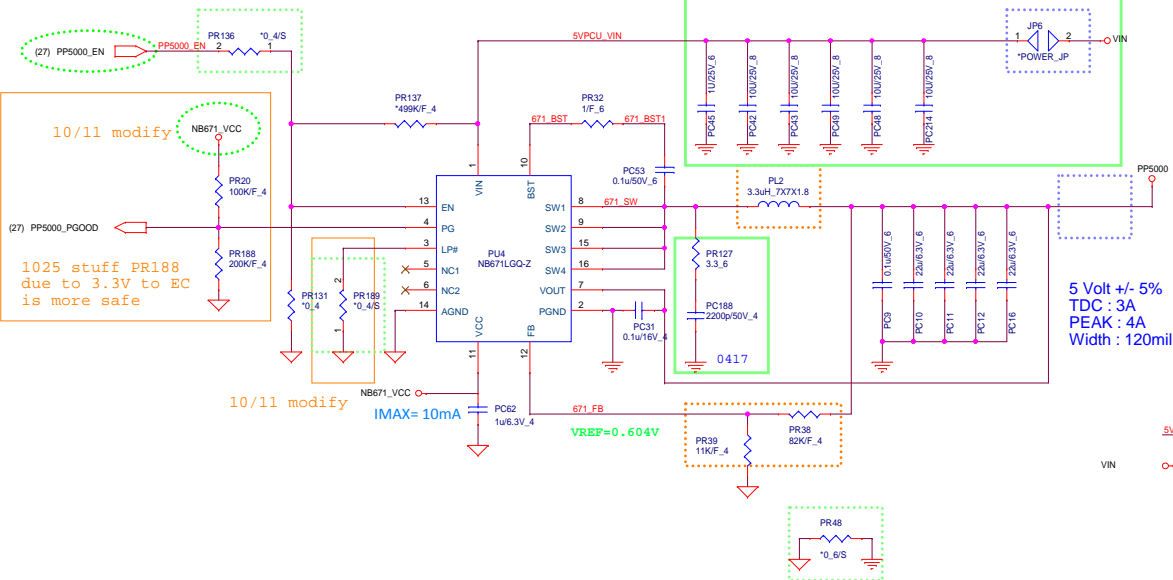
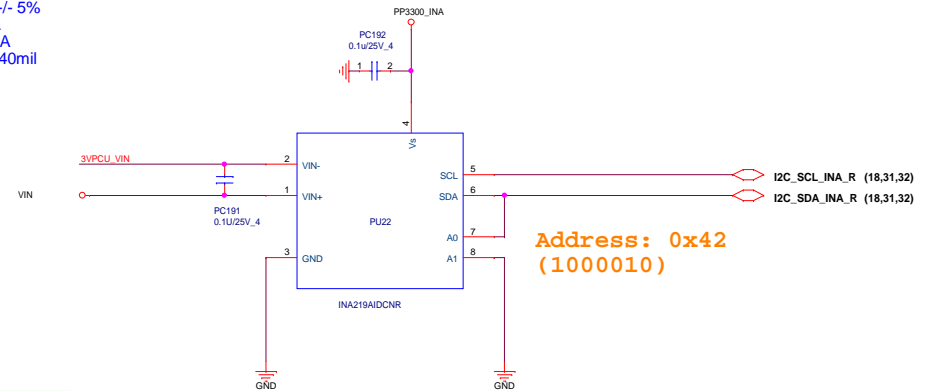
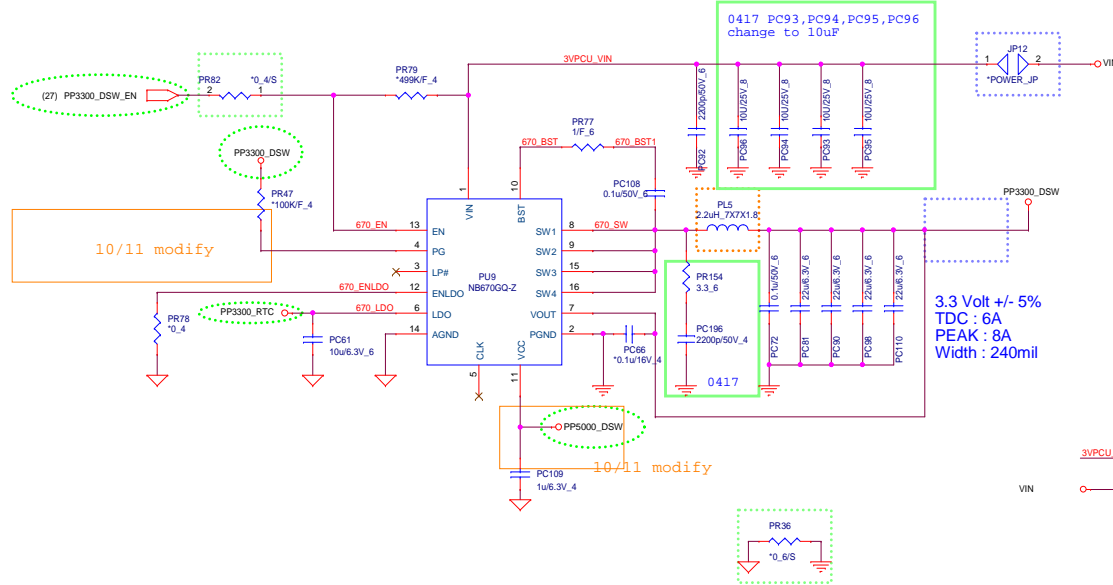
EC_REST_L
BAT_LED0
BAT_LED1
PCH_RSMRST_L
SMBUS
IRQ_SERIRQ
EC_BL_DISABLE_L

For testing only




Quanta Computer Inc.
PROJECT : NL6







 <div> <div>Quanta Computer Inc.</div> <div>PROJECT :</div> </div>		
Size	Document Number Load Switch	Rev 1A
Date:	Friday, April 25, 2014	Sheet 30 of 40

TDC : 0.75A
PEAK : 1A
Width : 10mil

TDC : 0.38A
PEAK : 0.5A
Width : 20mil

Greater than or equal 40mil

0417 PC13 change to 10uF ,
add 2x10uF PC215 , PC216

1.35 Volt +/- 5%
TDC : 3.55A
PEAK : 4.73A
OCP : 6A
Width : 160mil

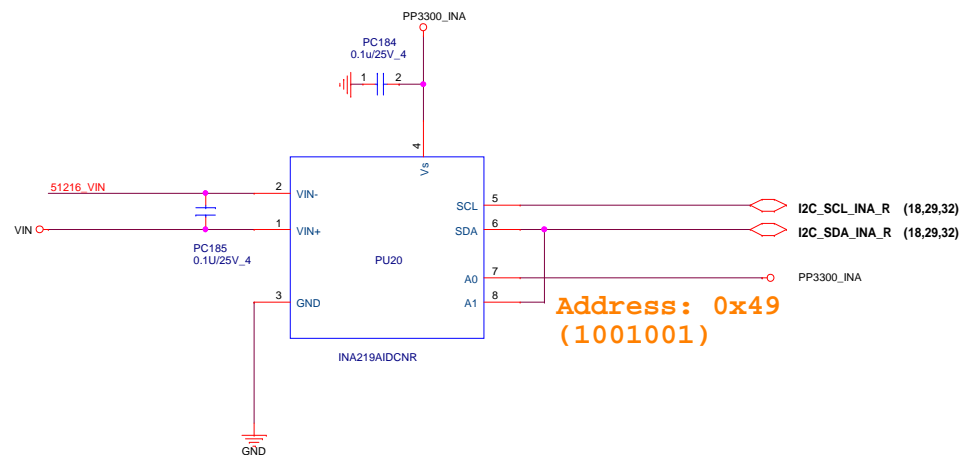
Close to output cap

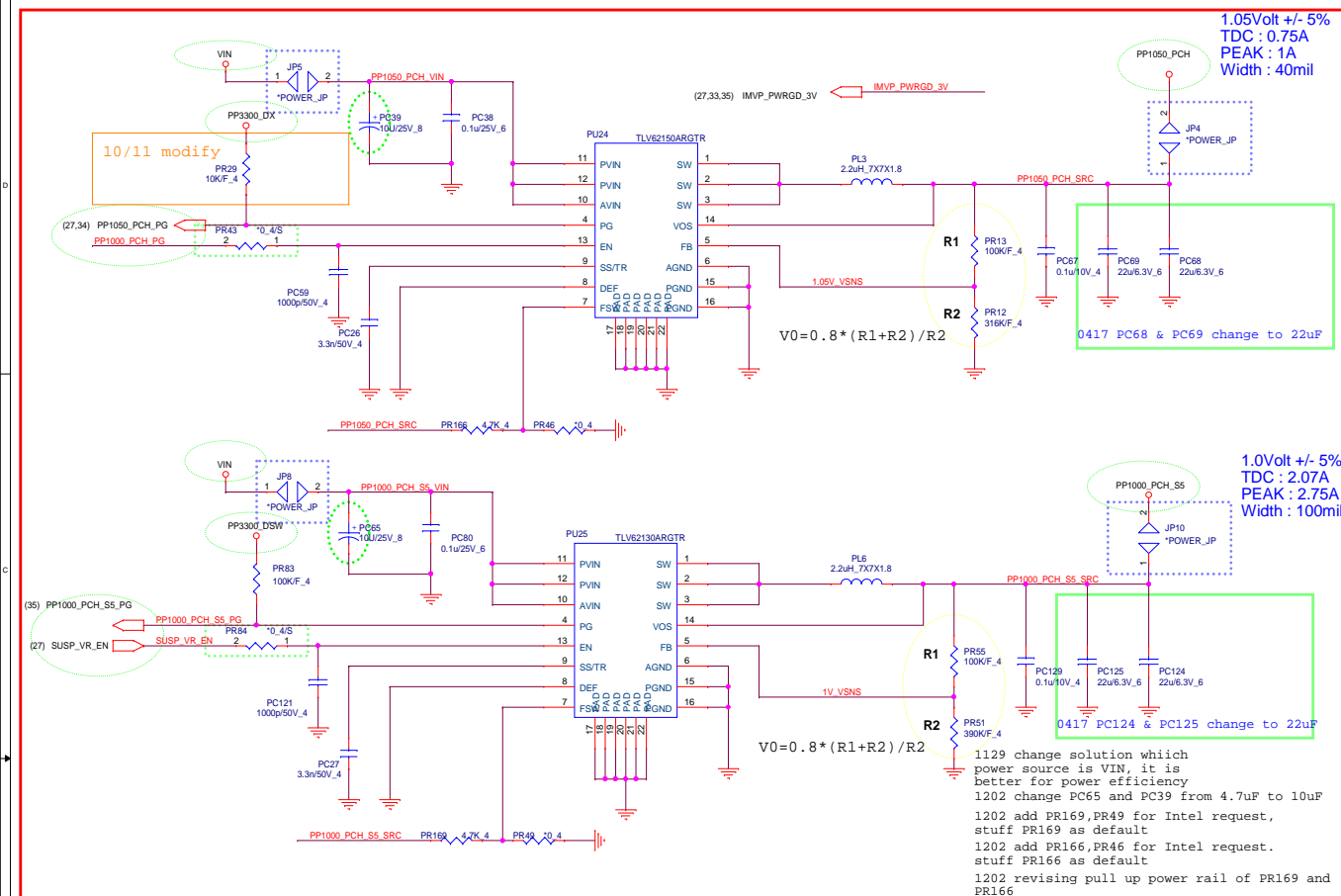
0417 PR21 change to 3.3ohm ,
PC32 change to 1200uF , PC29
change to 10uF

OCP=6A
L ripple current
= $(19-1.35) \times 1.35 / (2.2 \times 400 \times 19)$
=1.425A
 $V_{trip} = [6 - (1.425/2)] \times 14 \text{mohm}$
=0.07402V
 $R_{limit} = 0.07402 / 10 \mu\text{A} \times 8 = 59.22 \text{Kohm}$

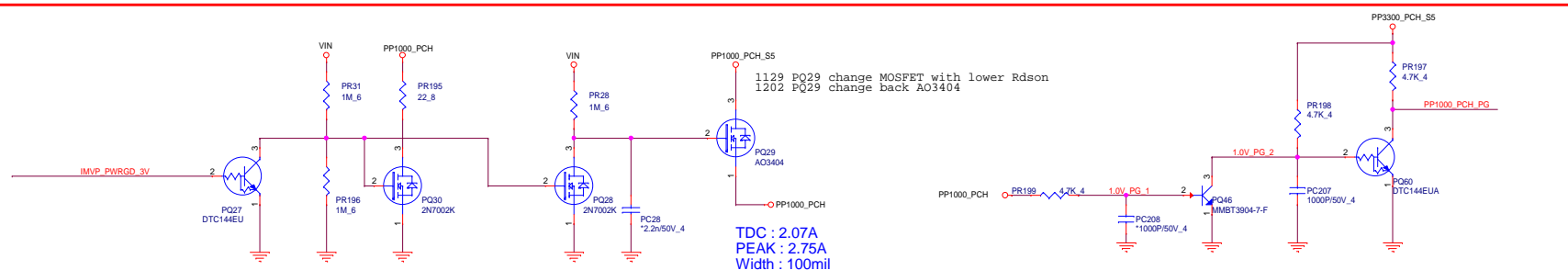
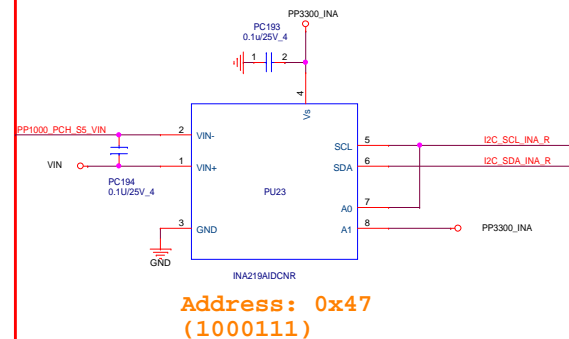
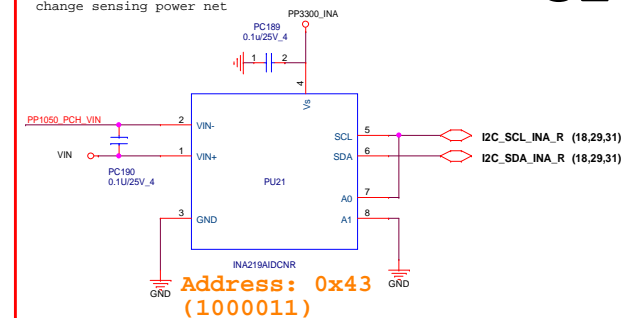
Mode	Frequency	Discharge mode
200K	400K	Tracking Discharge
100K	300K	Tracking Discharge

	S3	S5	+1.35VSUS	REF	VTT
S0	1	1	ON	ON	ON
S3 (main on off)	0	1	ON	ON	OFF
S4/S5	0	0	OFF	OFF	OFF





1129 because of power source of PU24, PU25 chagen to VIN, so that need change sensing power net

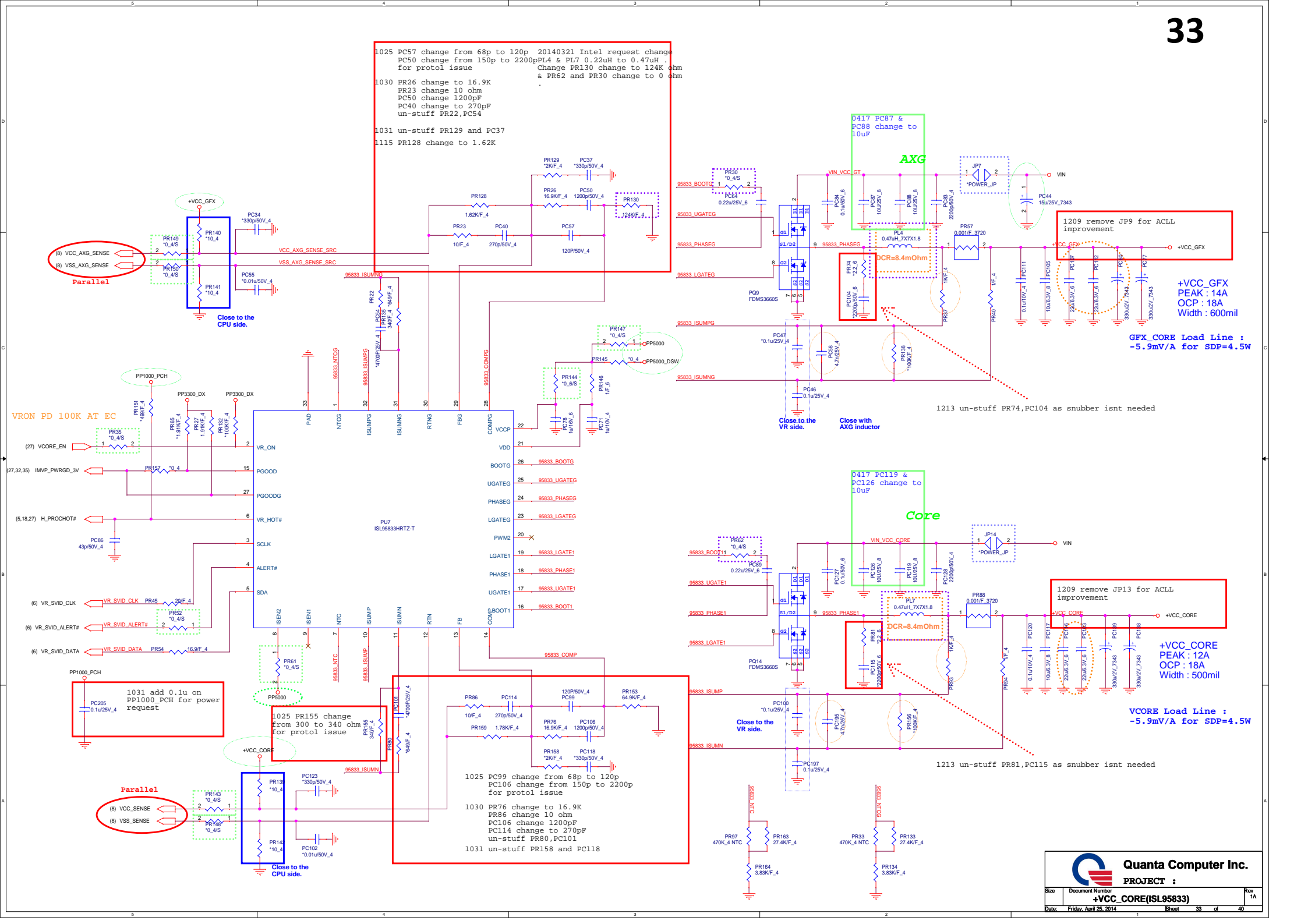


1129 PP1000_PCH changes from convert to power MOSFET type for power efficiency improvement

1025 PC99 change from 68p to 120p
PC106 change from 150p to 2200p
for protol issue

1030 PR76 change to 16.9K
PR86 change 10 ohm
PC106 change 1200pF
PC114 change to 270pF
un-stuff PR80, PC101

1031 un-stuff PR158 and PC118



PP3500_DSW

PP3300_DSW

PP1800_PCH_PG (35)

PP1800_PCH

PP3500

PR110 0.4/S

PR109 0.4

PC179 1u/16V_6

PP3300_DSW

PC182 10u/5.3V_6

PC181 0.1u/50V_6

PC183 0.1u/50V_6

PC180 10u/5.3V_6

PR116 100K_4

PP3300_DX

PP1800_PCH_PG (35)

PP1800_PCH

PR114 43.2K/F_4

PR113 34K/F_4

0.8v

R1

R2

PU19 G9691-25ADJF12U

VPP 4

PGOOD 1

VEN 2

VO 6

VIN 3

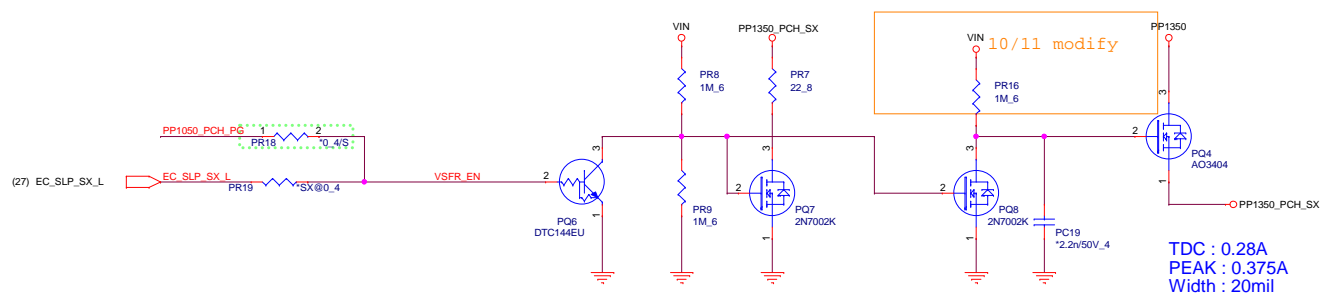
GND 8

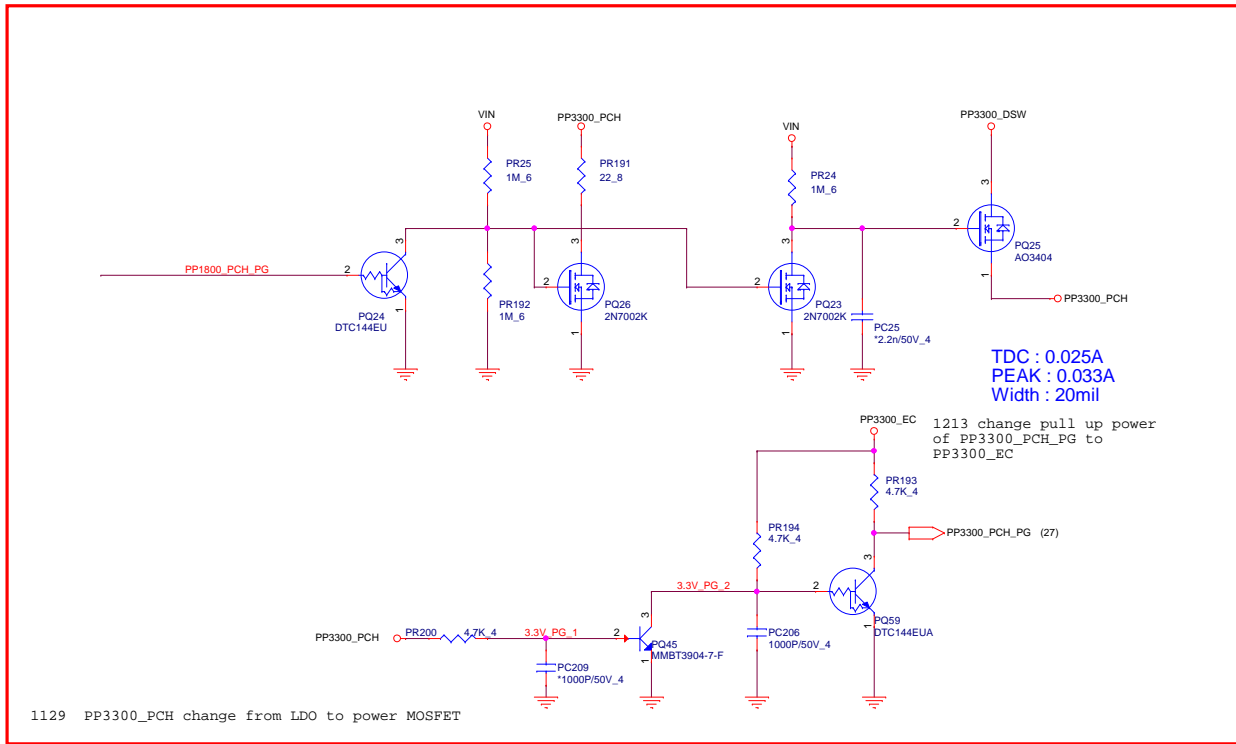
ADJ 5

NC 7

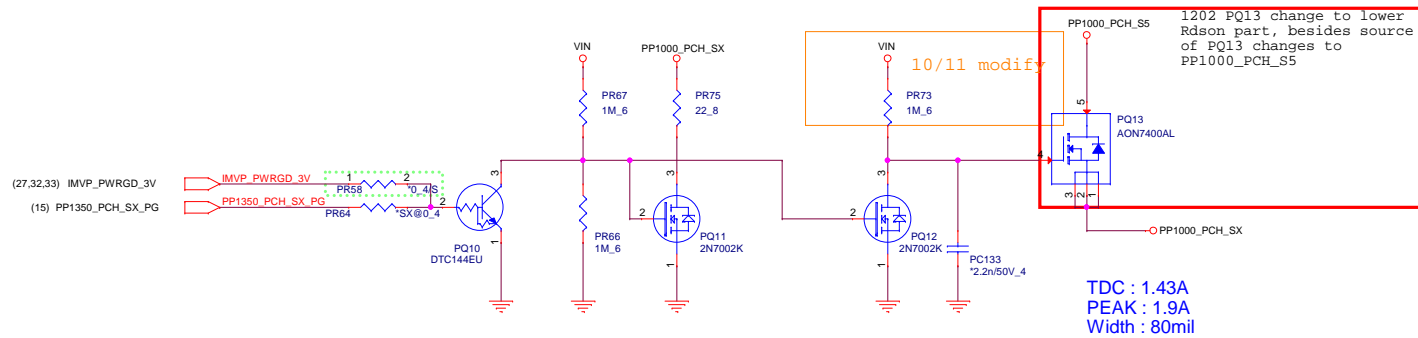
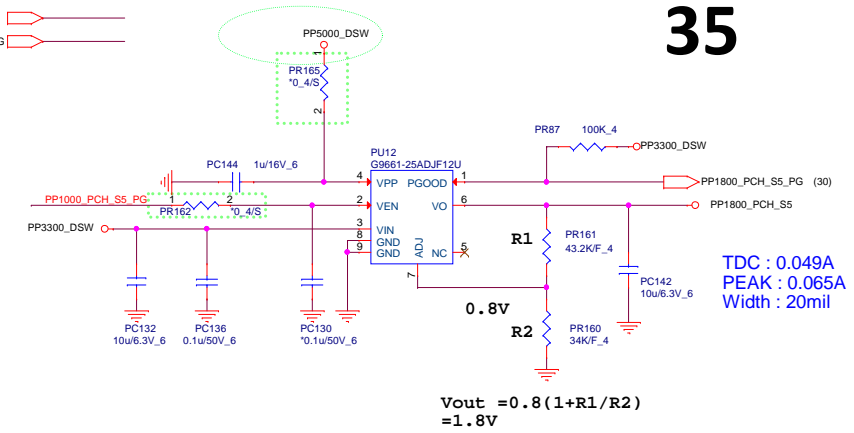
TDC : 0.026A
PEAK : 0.035A
Width : 20mil

$$V_{out} = 0.8(1 + R1/R2) = 1.8V$$





(34) PP1800_PCH_PG
(32) PP1000_PCH_S5_PG

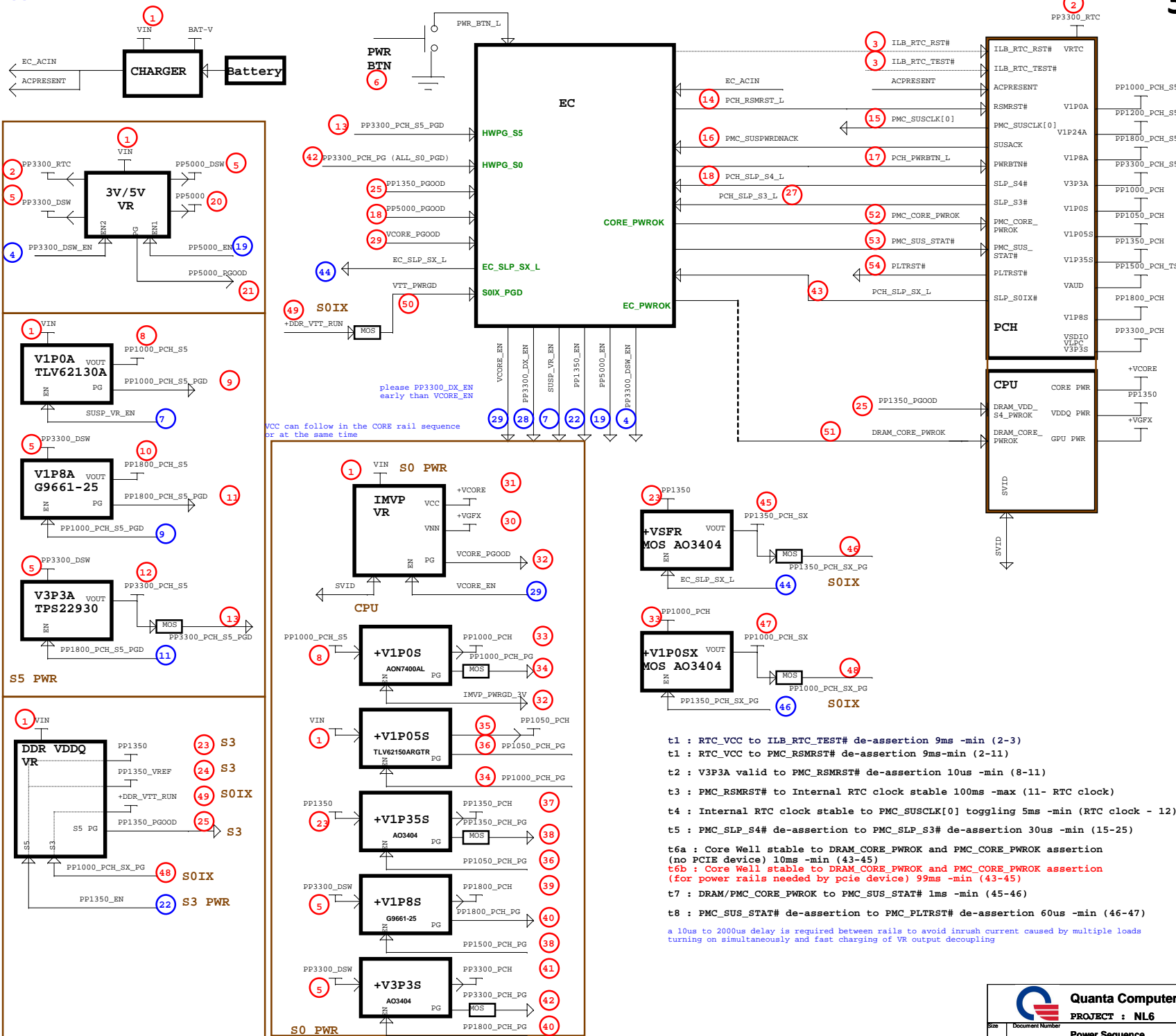




Quanta Computer Inc.

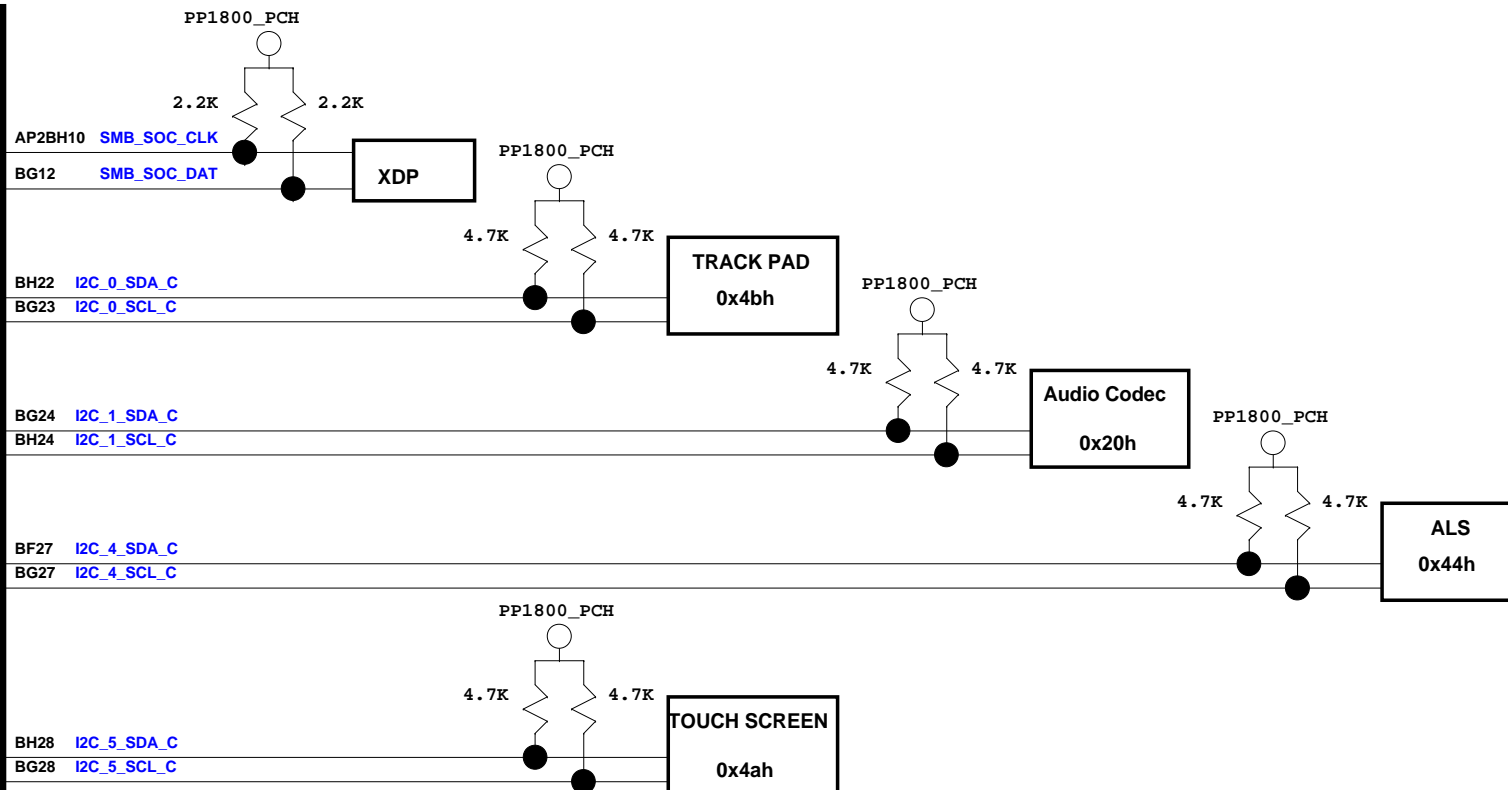
PROJECT :

Size	Document Number	Rev
	Thermal protect	1A
Date:	Friday, April 25, 2014	Sheet 36 of 41

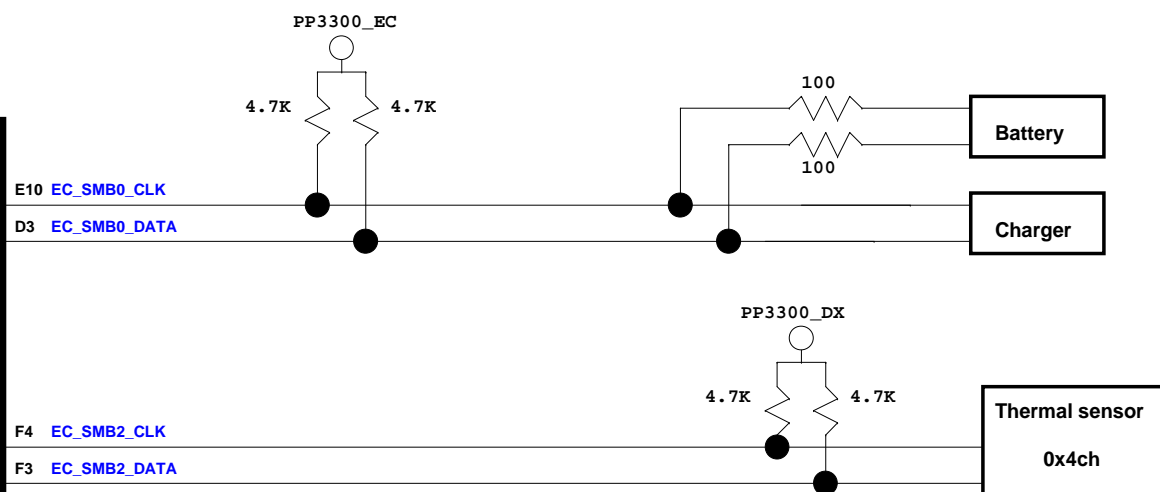


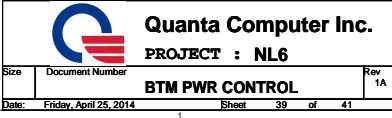
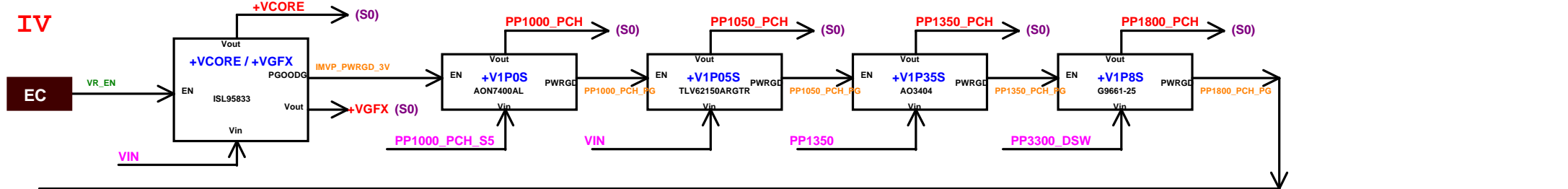
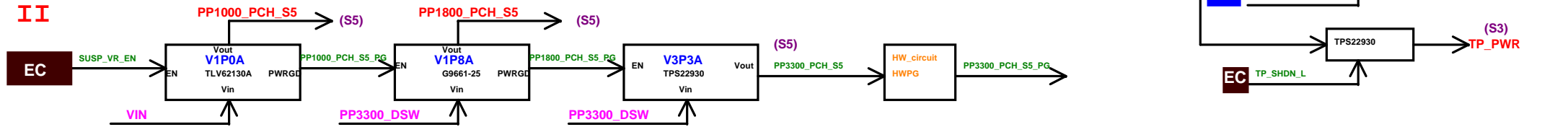
SMBUS
Bay-trail M

I2C



KBC
TI
SMBUS





Model Version CHANGE LIST

NL6

PVT1

2/20

- 1. un-stuff R156 for SERIRQ skipped (Page14)
- 2. change power rail of Q35,Q36,Q37,Q44 from PP1800_PCH_S5 to PP1800_PCH for PP1800_PCH leakage issue in S3 mode (Page14)
- 3. unstuff R337 for S3 leakage issue(Page 11)
- 4. Delete LED2, R127 (Page 22,27)
- 5. Change LED1 type to right angle , same as 0C7 (Page22)
- 6. unstuff R454,Q33,Q144 for auto power on issue when insert battery first time(Page 26)
- 7. change PR130 to 124K ohm for efficiency improvement (Page 33)
- 8. change PL7/PL4 to 0.47uH and PR30/PR62 to 0ohm for efficiency improvement (Page 28)
- 9. unstuff NUT of Hole4,Hole5(Page 25)

PVT2

3/19

- 1. Disconnect SPI SIO I/F (Page6, 27)
- 2. Delete SPI_SIO Interface,Q35,Q36,Q37,Q44,R486,R484,R485,R483,R426,R429,R427,R428 (Page14)
- 3. reserve C377 on SD CLK for EMI (Page 5)
- 4. reserve R483 for CLKRUN# disable (Page 7)
- 5. change level shifter of PMC_SUSCLK1,LTE_DISABLE#,LTE_WAKE#,PMC_SUSCLK0,SOC_PMC_WAKE#,WIFI_DISABLE# to double inverter for S3 leakage issue (Page 15)
- 6. stuff C372 for EMI issue(Page 16)
- 7. add PD13 for S3 leakage(Page 28)
- 8. reserve C330 for EMI request (Page 25)
- 9. reserve placeholder R212,R218 for additional RAM ID (Page 7)
- 10. change bi-direction level shifter of LTE_DISABLE#,LTE_WAKE#,SOC_PMC_WAKE#,WIFI_DISABLE# to double inverter for S3 leakage issue, and PMC_SUSCLK0 and PMC_SUSCLK1 to buffer type (Page 15)
- 11. Reserve load switch(U1007,C391,R623) for touch screen power(Page 17)
- 12. reserve R91 0 ohm on SIM_DET line for difference design of various cards(Page 15)
- 13. Change below 0 ohm to short pad for cost saving:
0402: R180,R197,R204,R123,R131,R139,R455,R462,R103,R414,R383,R375,R381,R379,R183,R452,R457,R58,R165,R468,R448,R107,R424,R449,R343,R385,R54,R378,R380,R430,R456,R110,R114,R121,R395,R400,R407,R453,R464,R460,R319,R320,R332,R263,R333,R171,R174,R137,R10,R11,R13,R326,R341,R339,R20,R46,R411,R51,R60,R72,R57,R370,R67,R194,R244,R390,R213,R546,R227,R173,R169
0603: R116,R157,R193,R555,R14,R224,R355,R229,R232,R235,R241,R217,L7,R206
0805: R354,R384,R17,R39
- 14. Change LED1 to Green/Orange
- 15. Change C78 to 220uF
- 16. Add C393 2.2uF at Q33 pin2, change R414 to 1Mohm
- 17. Add D23 for Pp5000